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Nanostructure Stability and Wear of Binary Nanocrystalline Alloys

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The Land of Enchantment

Sandia Mountains at Sunset



Balloon Fiesta



Green Chile



Sandia National Labs

Sandia – New Mexico



Sandia – California

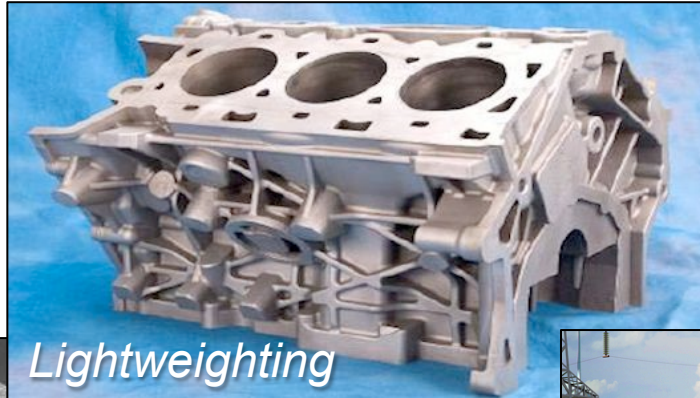


Outline

- Intro
- Prospects for Nanocrystalline (NC) Metals
- Challenges to Application of NC Metals
- Solute Segregation for Stabilization of NC Metal Alloys
- Stability under Wear in NC Ni-W
- Recent Stability Results in NC Pt-Au
- Future Outlook

Aren't We “Done” with Metals?

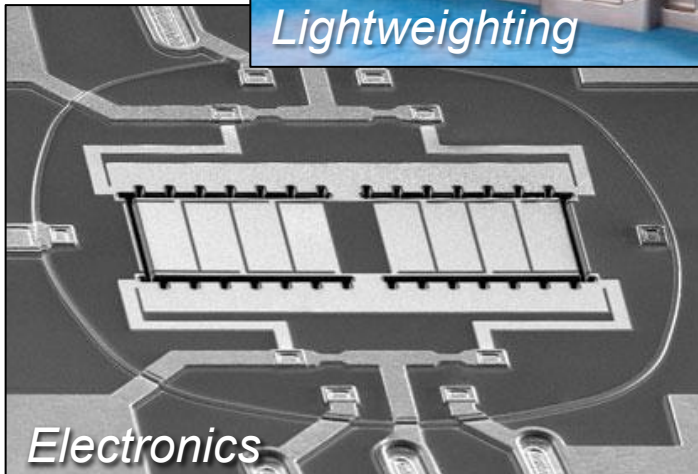
Metals are Integral to Innovation



Lightweighting

Strong demand to:

- Maximize performance
- Extend lifetimes
- Engineer properties 'by design'



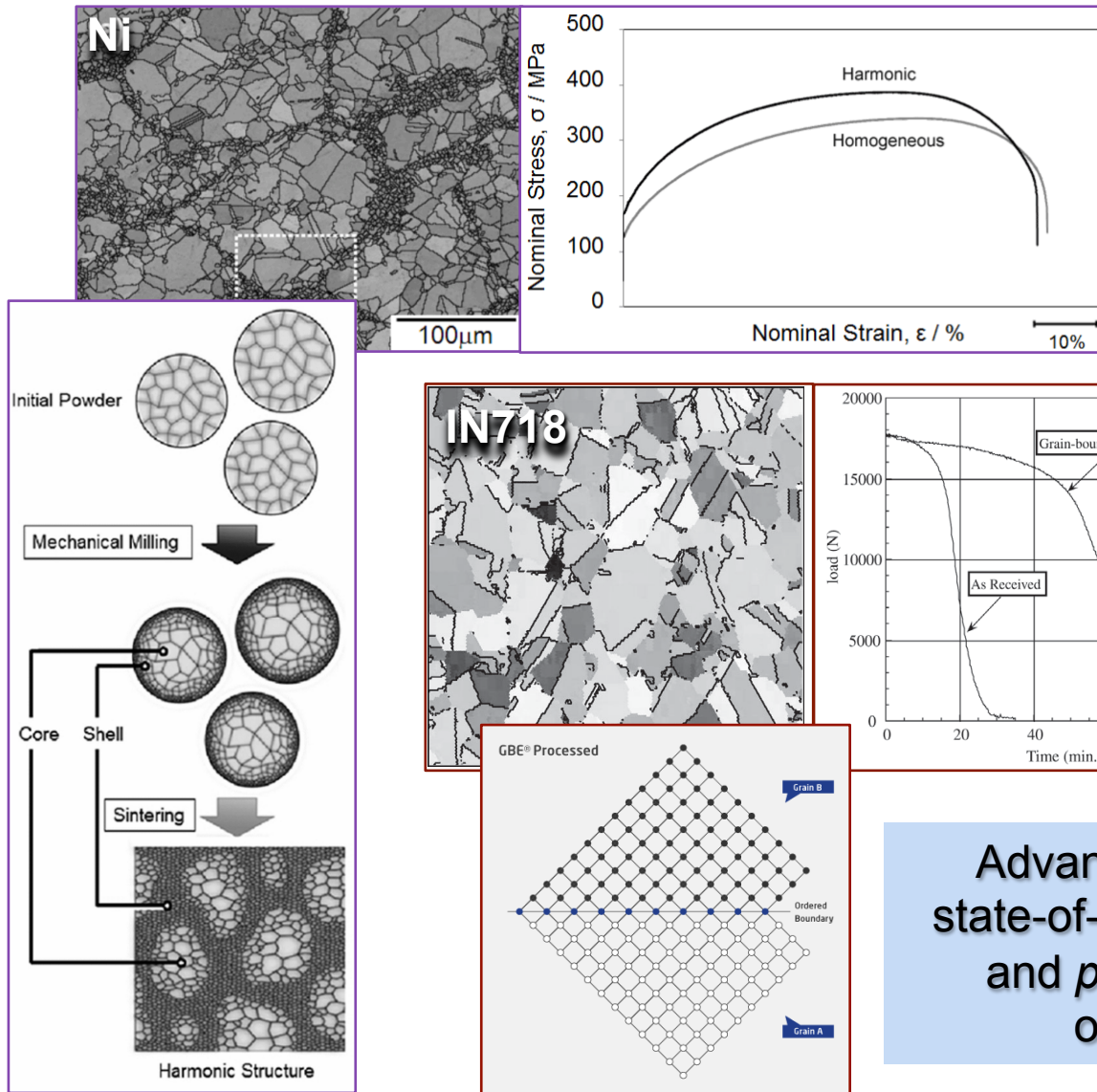
Electronics



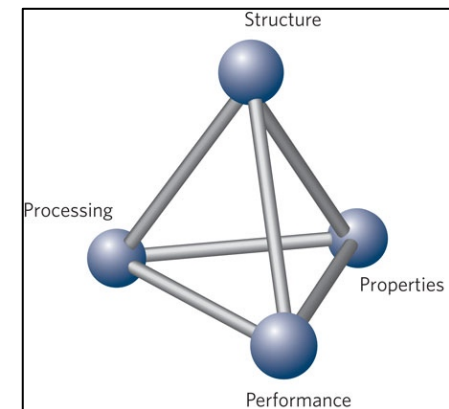
Alternative energy & storage

Advanced experimental and computational methods are enabling *re-exploration* of decades-old questions and *new understanding* of complex phenomena in metals

Achieving Properties 'By Design'

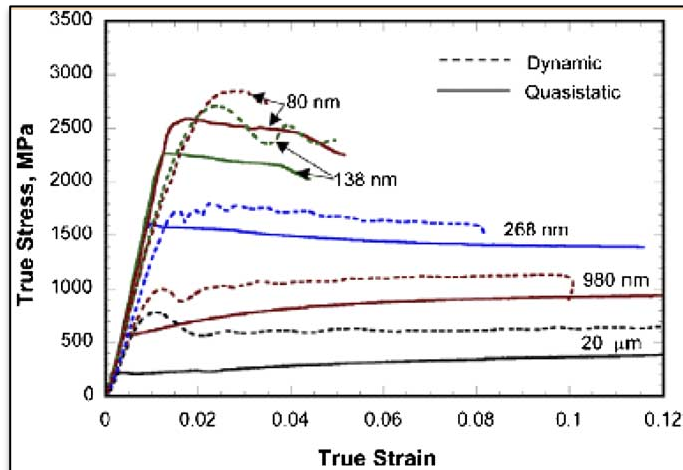


- Leveraging our physical understanding of fundamental interrelationships → *properties 'by design'*



Advanced processing coupled with state-of-the-art microstructural analysis and *physical understanding* of the origin of properties is key

Nanocrystalline Advantages

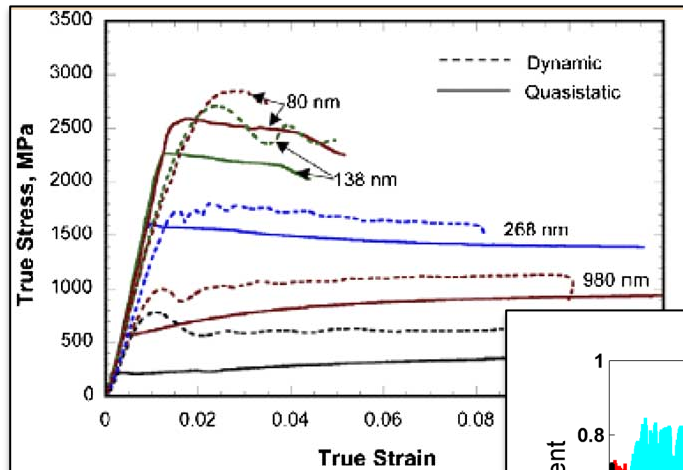


- Nanocrystalline (NC) metals have many advantages...

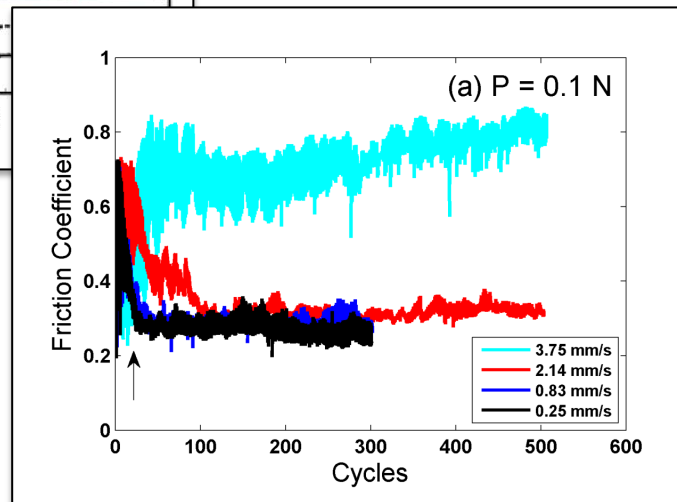
Increased
strength

Nanocrystalline Advantages

- Nanocrystalline (NC) metals have many advantages...



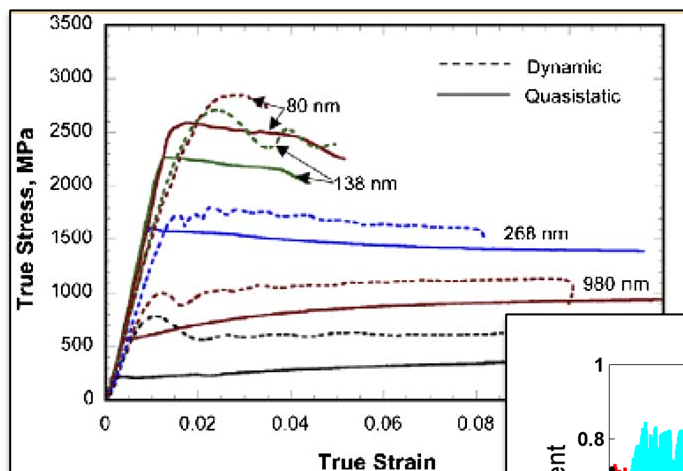
Increased strength



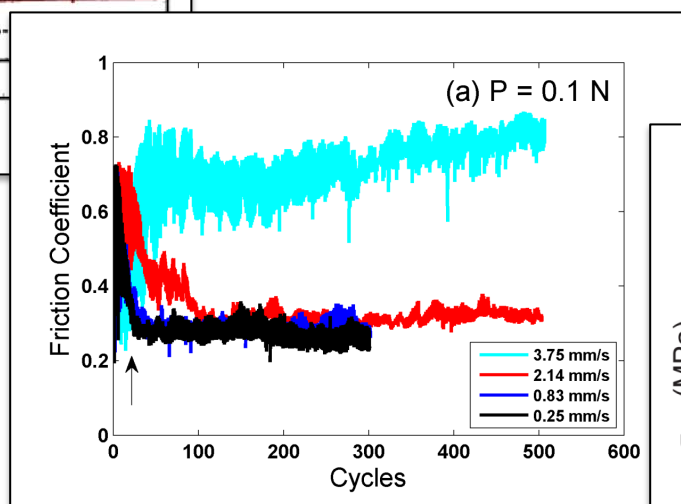
Lower friction coefficient

Nanocrystalline Advantages

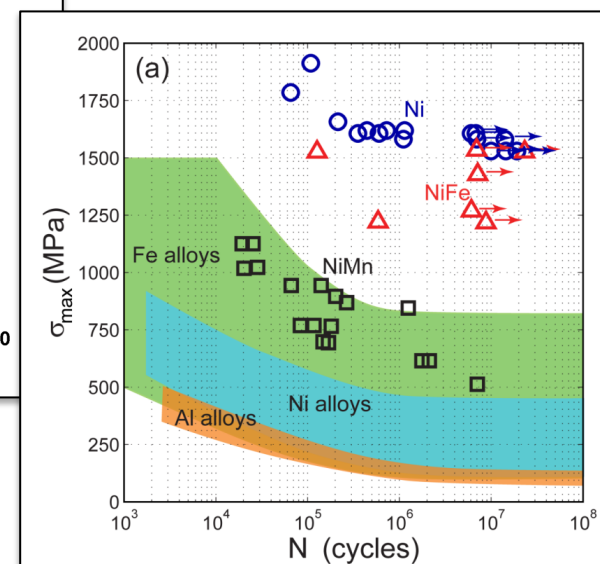
- Nanocrystalline (NC) metals have many advantages...



Increased strength

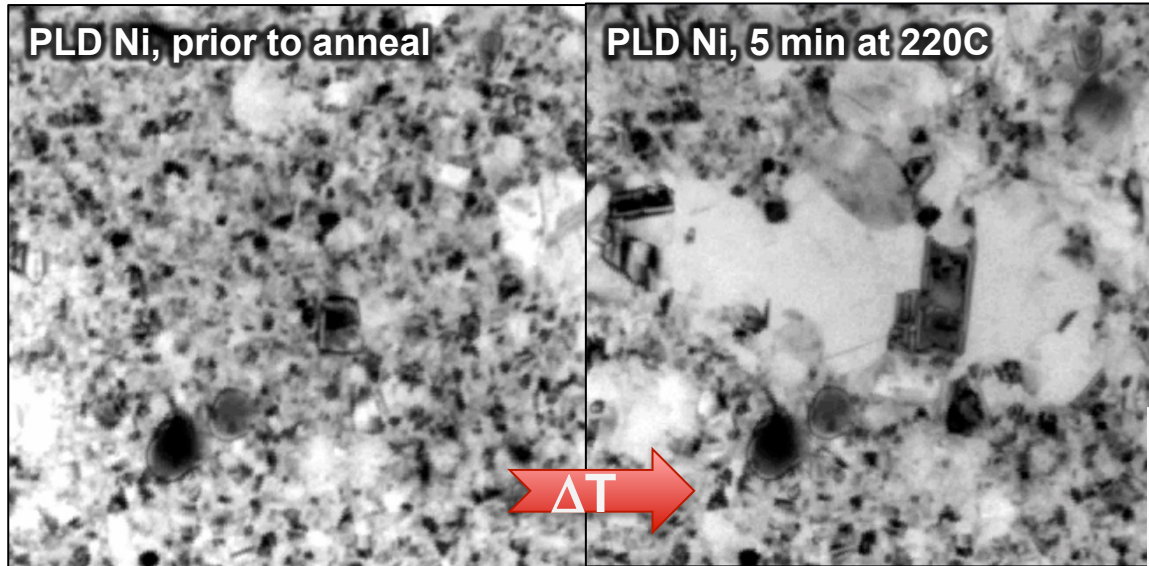


Lower friction coefficient



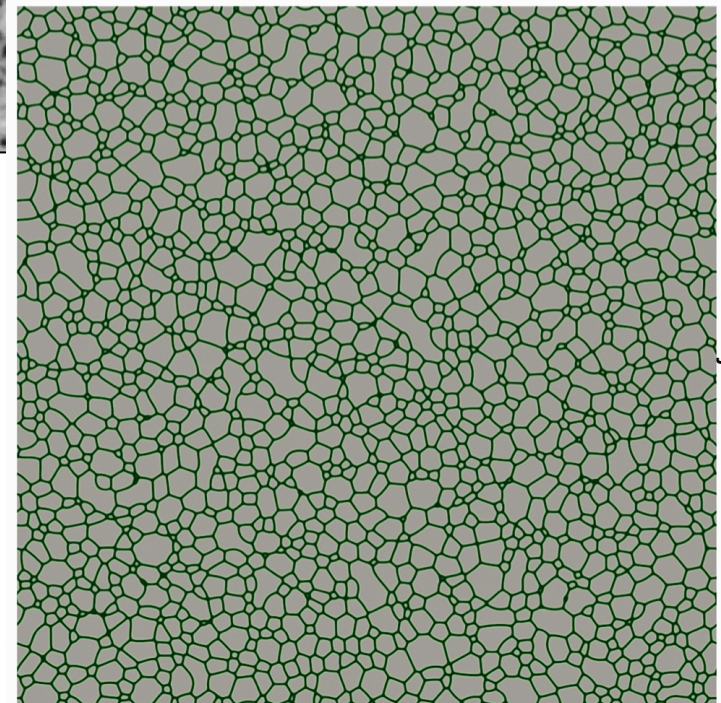
Enhanced fatigue performance

Challenge of Instability



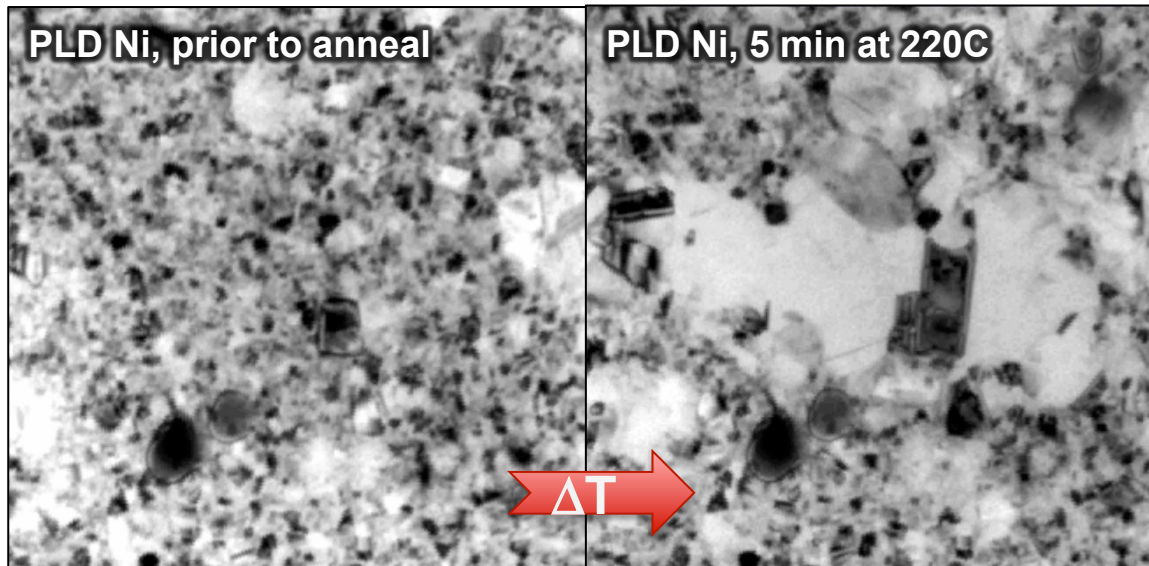
NC Metals are driven
to grain growth

Thermally...



Video credit: Fadi Abdeljawad

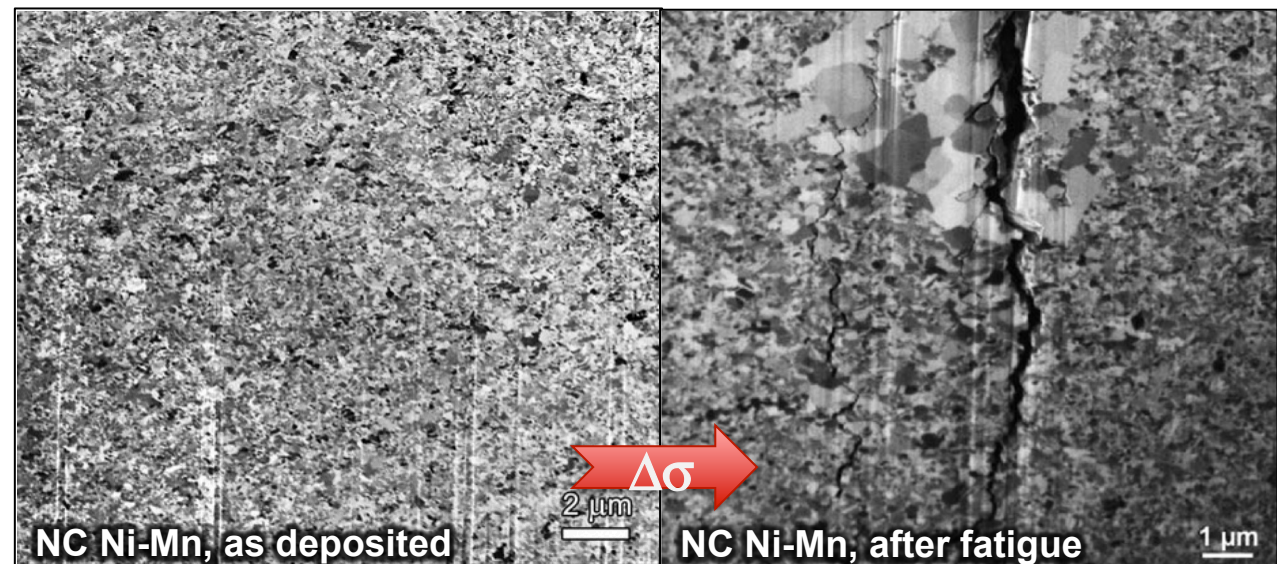
Challenge of Instability



NC Metals are driven
to grain growth

Thermally...

...and Mechanically



Two Routes to Stability

ref: Simoes et al., Nanotech. (2010)

Grain growth driven by boundary velocity, related to boundary mobility and applied stress



$$v = M \cdot P = M_o \exp\left(-\frac{Q_m}{kT}\right) \cdot \frac{2\gamma_o}{r}$$

M = grain boundary mobility

P = pressure on grain boundary

γ_o = interfacial energy per unit area

r = mean grain radius

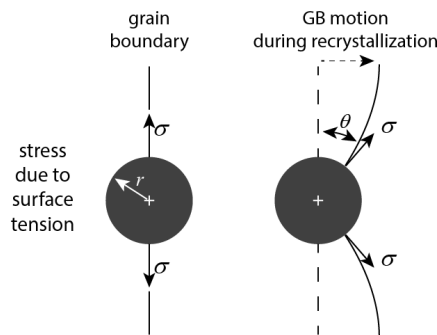
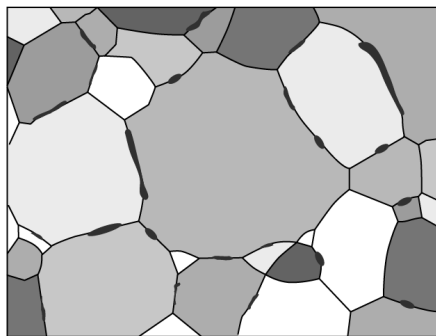
Two Routes to Stability

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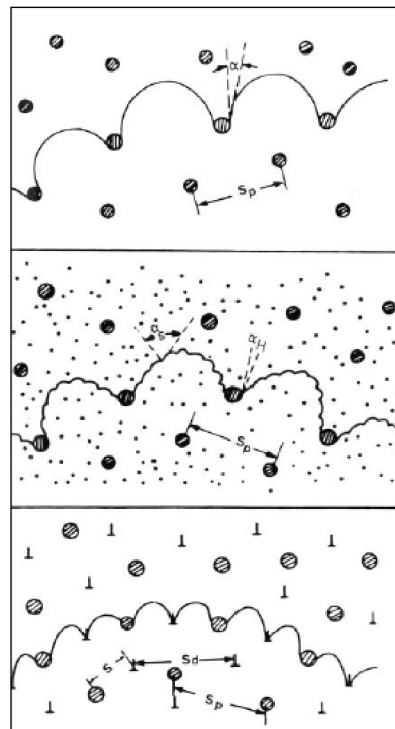
$$v = M \cdot P = M_o \exp\left(-\frac{Q_m}{kT}\right) \cdot \frac{2\gamma_o}{r}$$

Limit the *kinetics* of recrystallization (traditional quasi-stability)

e.g. Zener pinning, solute drag, porosity



drag force: $f_D = 2\pi r \sigma \cos \theta \sin \theta$



M = grain boundary mobility

P = pressure on grain boundary

γ_o = interfacial energy per unit area

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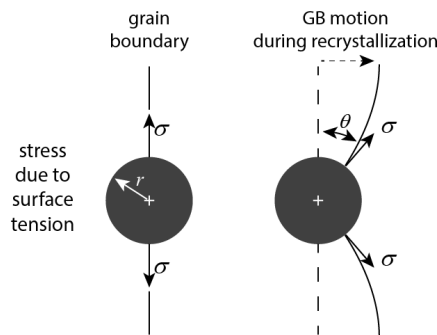
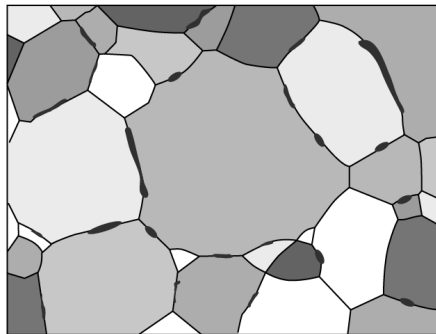
Two Routes to Stability

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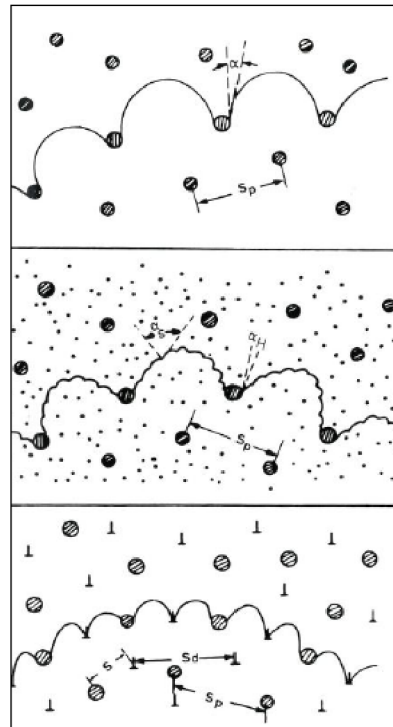
$$v = \boxed{M} \cdot \boxed{P} = M_o \exp\left(-\frac{Q_m}{kT}\right) \cdot \boxed{\frac{2\gamma_o}{r}}$$

Limit the **kinetics** of recrystallization (traditional quasi-stability)

e.g. Zener pinning, solute drag, porosity



drag force: $f_D = 2\pi r \sigma \cos \theta \sin \theta$



M = grain boundary mobility

P = pressure on grain boundary

γ_o = interfacial energy per unit area

r = mean grain radius

Weissmüller (1993), Kirchheim (2002), and Schuh (2012) have made significant contributions toward understanding and achieving **thermodynamic** stability by lowering grain boundary energy through solute segregation

Regular Nanocrystalline Solution (RNS) Model:

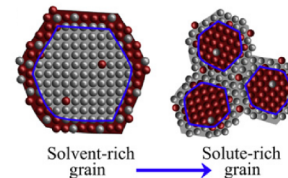
ref: Chookajorn et al., Science, 2012

$$\Delta G^{\text{mix}} = (1 - f_{\text{gb}}) \Delta G_c^{\text{mix}} + f_{\text{gb}} \Delta G_{\text{gb}}^{\text{mix}} +$$

$$z v f_{\text{gb}} (X_{\text{gb}} - X_c) \left[(2X_{\text{gb}} - 1) \omega_{\text{gb}} - \right.$$

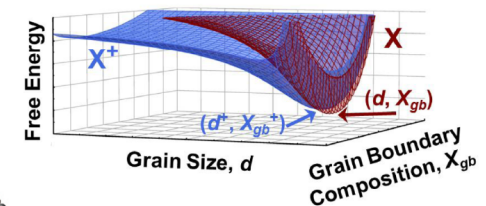
$$\left. \frac{1}{z t} (\Omega^B \gamma^B - \Omega^A \gamma^A) \right]$$

Grain structure model:
segregated 2-phase metal system



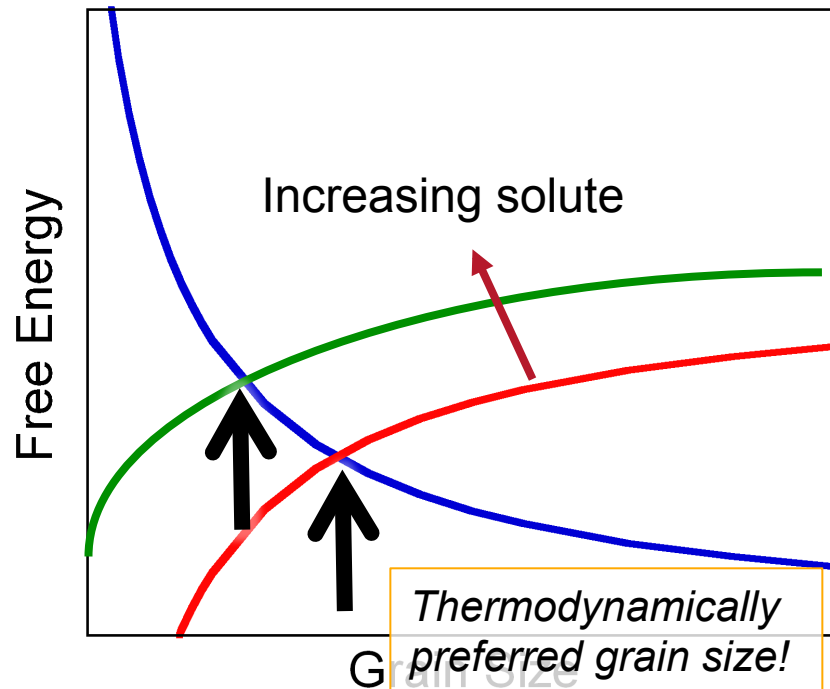
ref: Murdoch et al., Acta Mat. (2013)

$$dG = \left[\gamma - \frac{N_{\beta}}{A} \Delta G_{\text{seg}} \right] dA$$

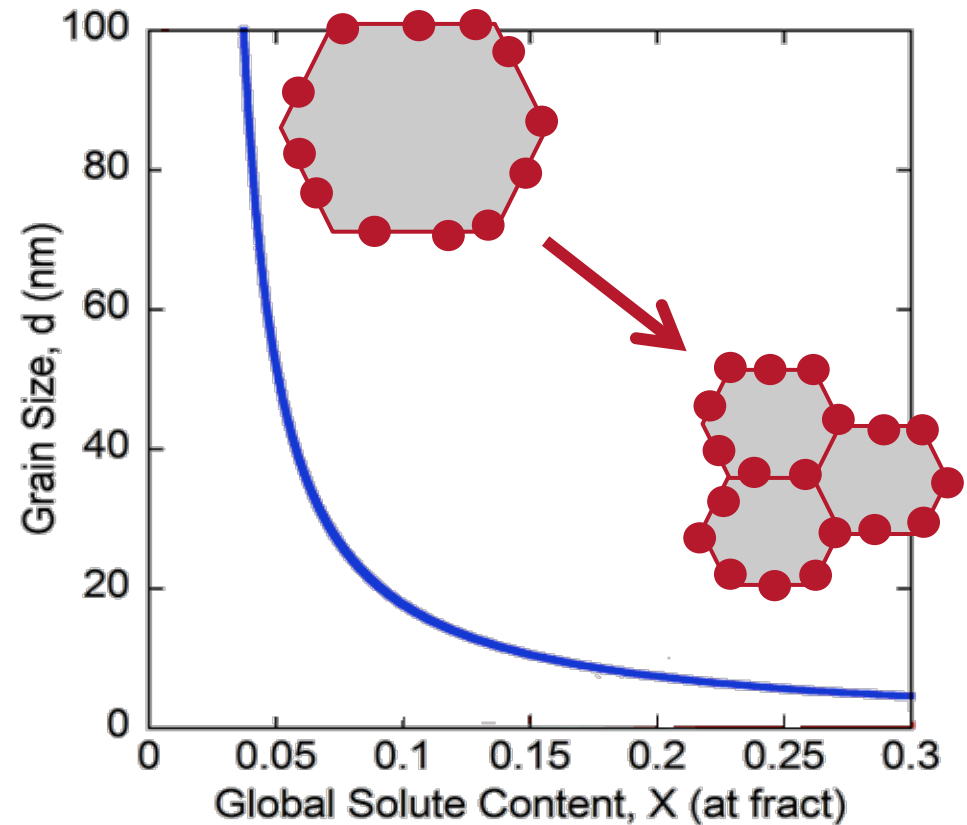


ref: Murdoch et al., Acta Mat. (2013)

Solute Segregation for Stabilization

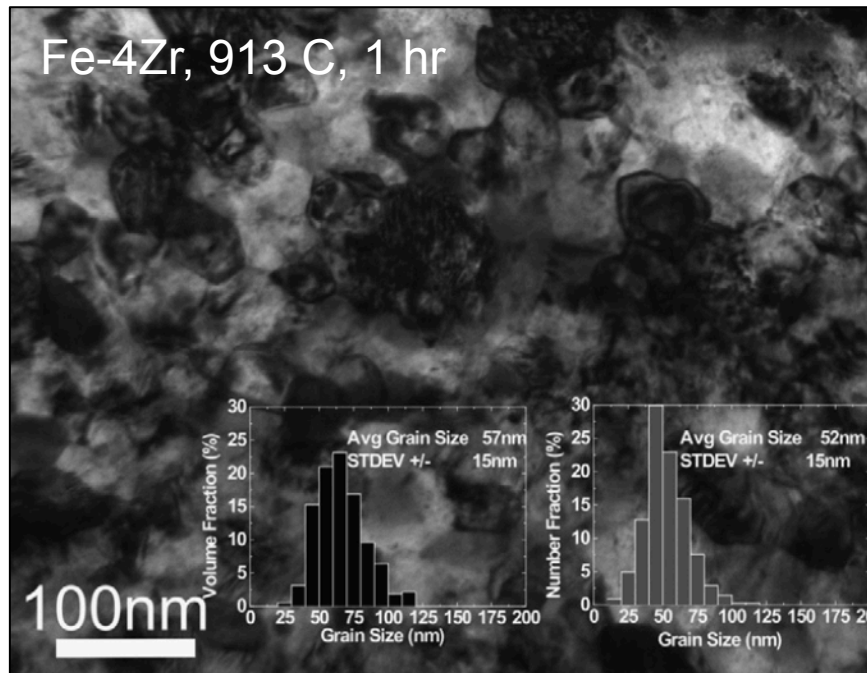


$$dG = \left[\gamma - \frac{N_{\beta}}{A} \Delta G_{seg} \right] dA$$

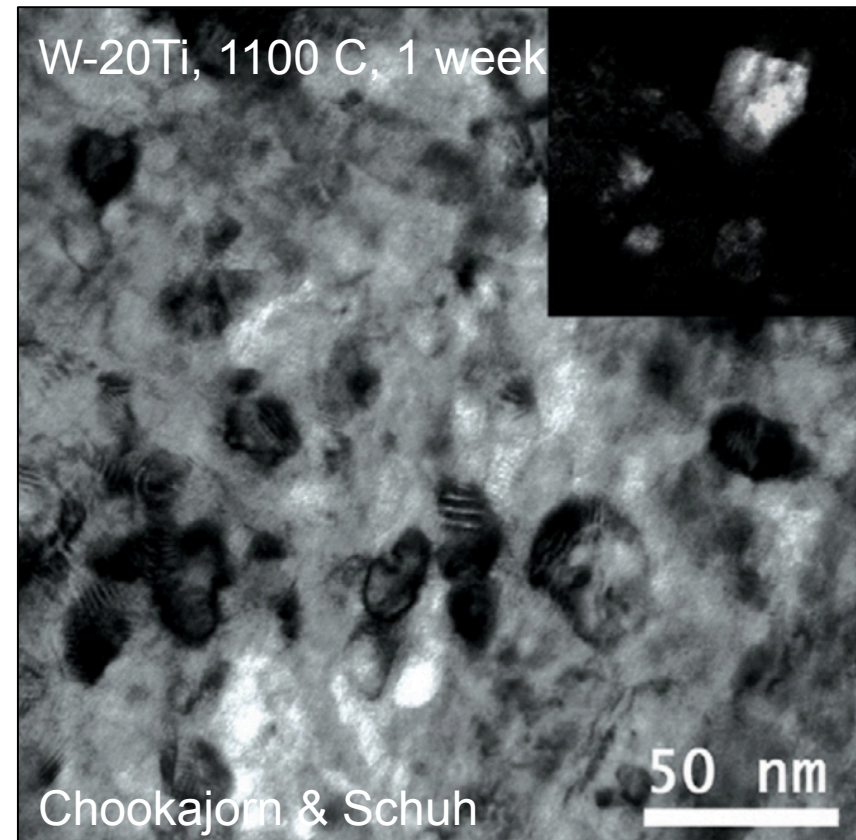


Increasing solute lowers the grain boundary energy
and reduces the grain size

Binary NC Alloys with Improved Thermal Stability



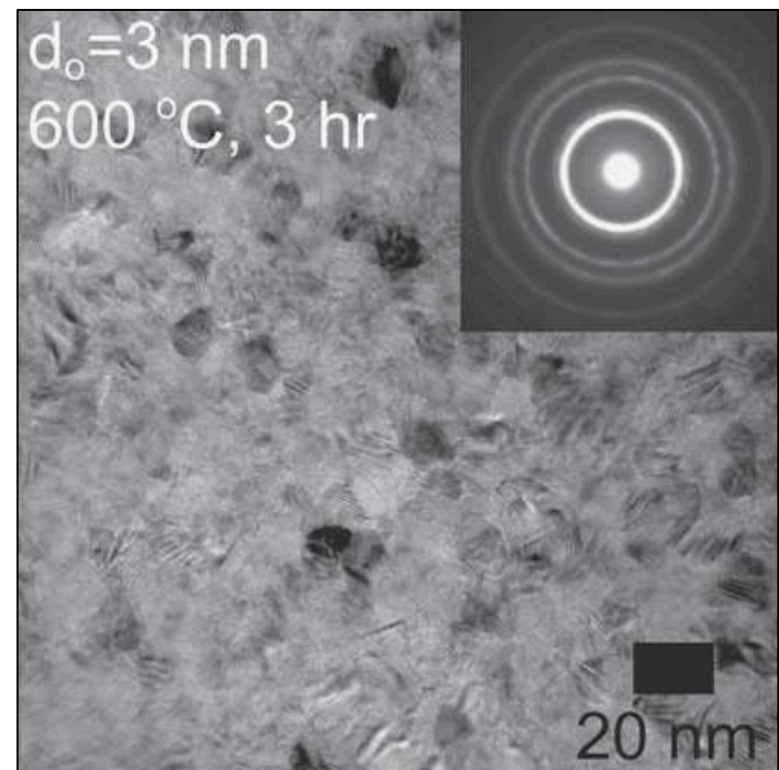
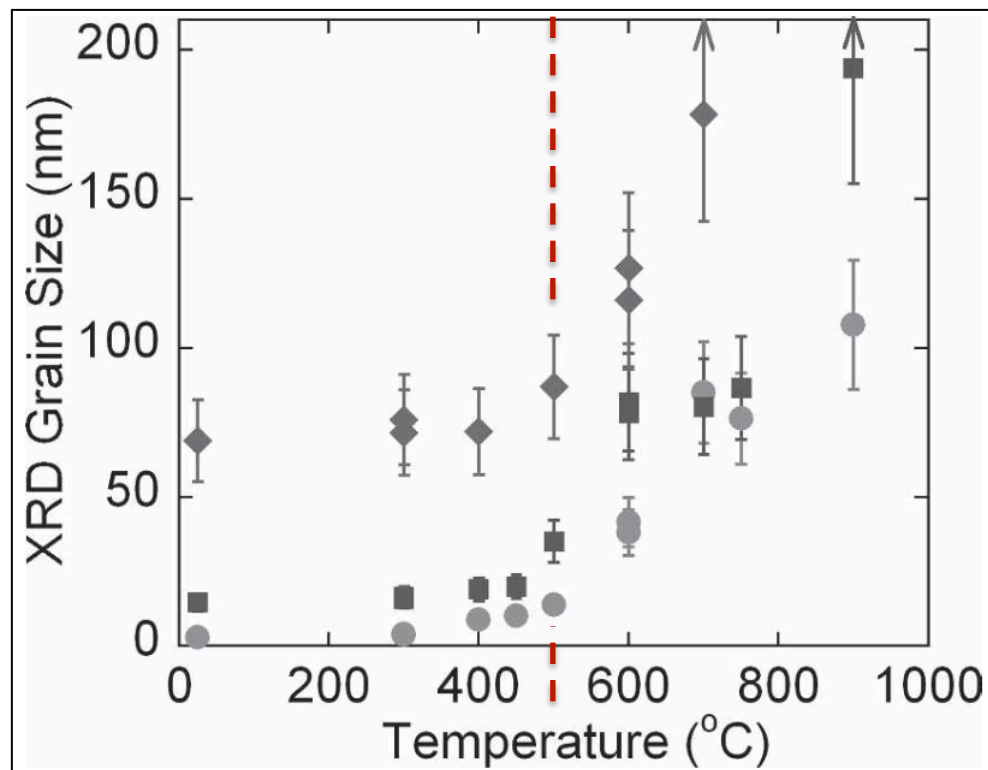
Darling et al.



Chookajorn & Schuh

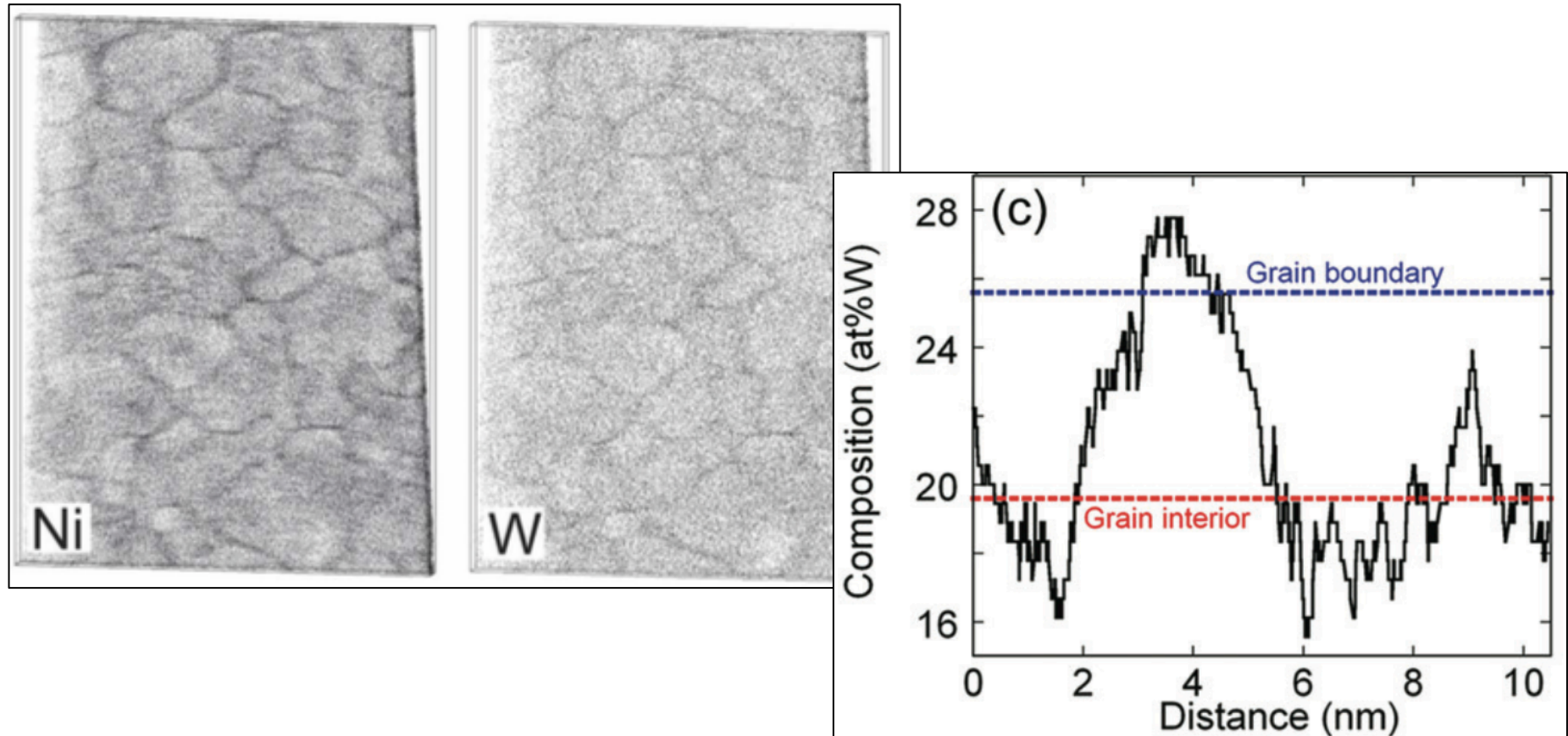
...plus examples of improved thermal stability in other NC alloys:
Ni-P, Cu-Ta, Ti-Cu, Pd-Zr, Fe-Mg, among others.

Ni-W: Improved Thermal Stability



Grain size remains stable during 24 h anneals up to 500 °C

Ni-W: Solute Segregation



Atom probe tomography shows W enriched at grain boundaries in Ni-W

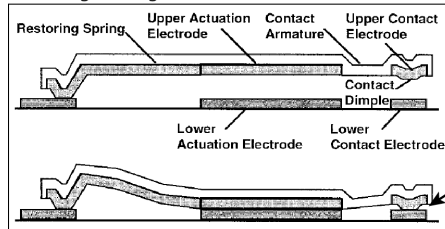
Ni-W demonstrated improved thermal stability...what about mechanical?

Does thermal stability correlate with stability under wear?

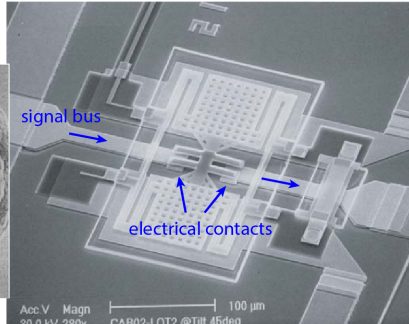
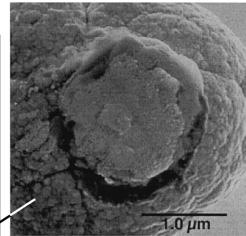
Motivation for Stability under Wear

RF Micro Electromechanical Systems (MEMS)

switching GHz signals



Source: D. Hyman and M. Mehregany, IEEE Trans. & Pack. Tech. 22-3, 1999



Source: Rockwell Scientific metal-metal switch

- Metals are widely used tribological materials

Electronics (e.g. PCB blade connectors):
200 - 500 nm thick electroless hard gold



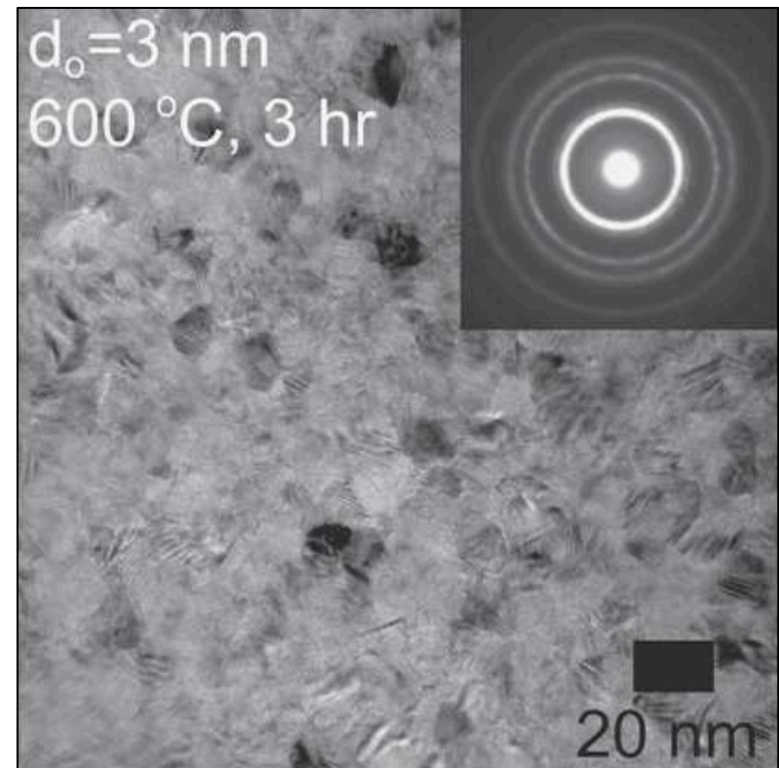
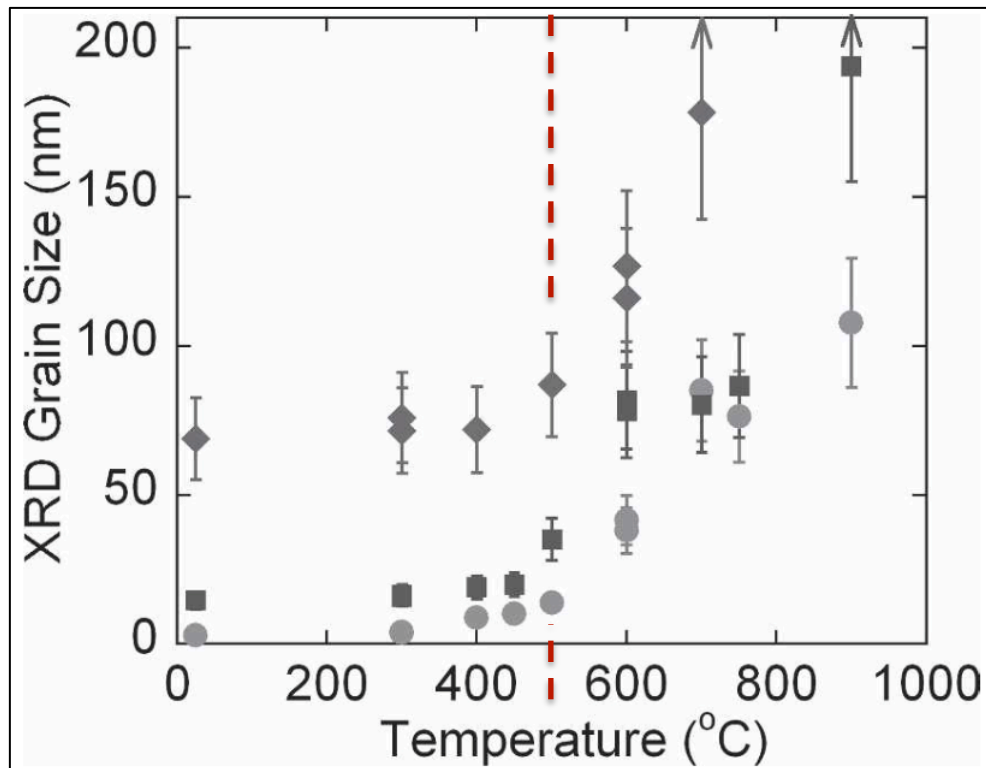
Aerospace and Energy



- Particularly for electrical contacts

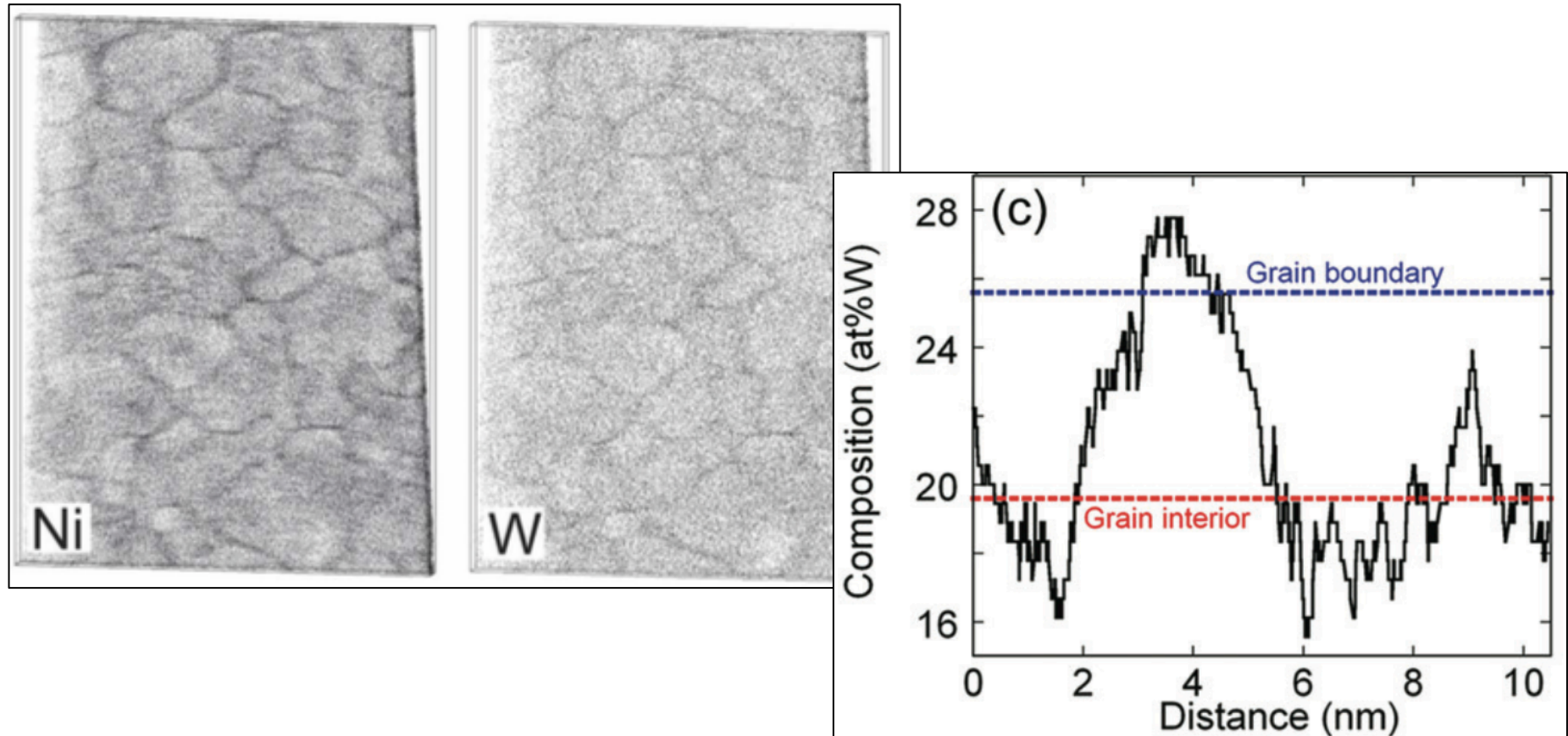
**Nanocrystalline metals well-suited for electrical contacts due to high hardness and thin film form
→ wear properties very important!**

Ni-W: Improved Thermal Stability



Grain size remains stable during 24 h anneals up to 500 °C

Ni-W: Solute Segregation



**Atom probe tomography shows W enriched
at grain boundaries in Ni-W**

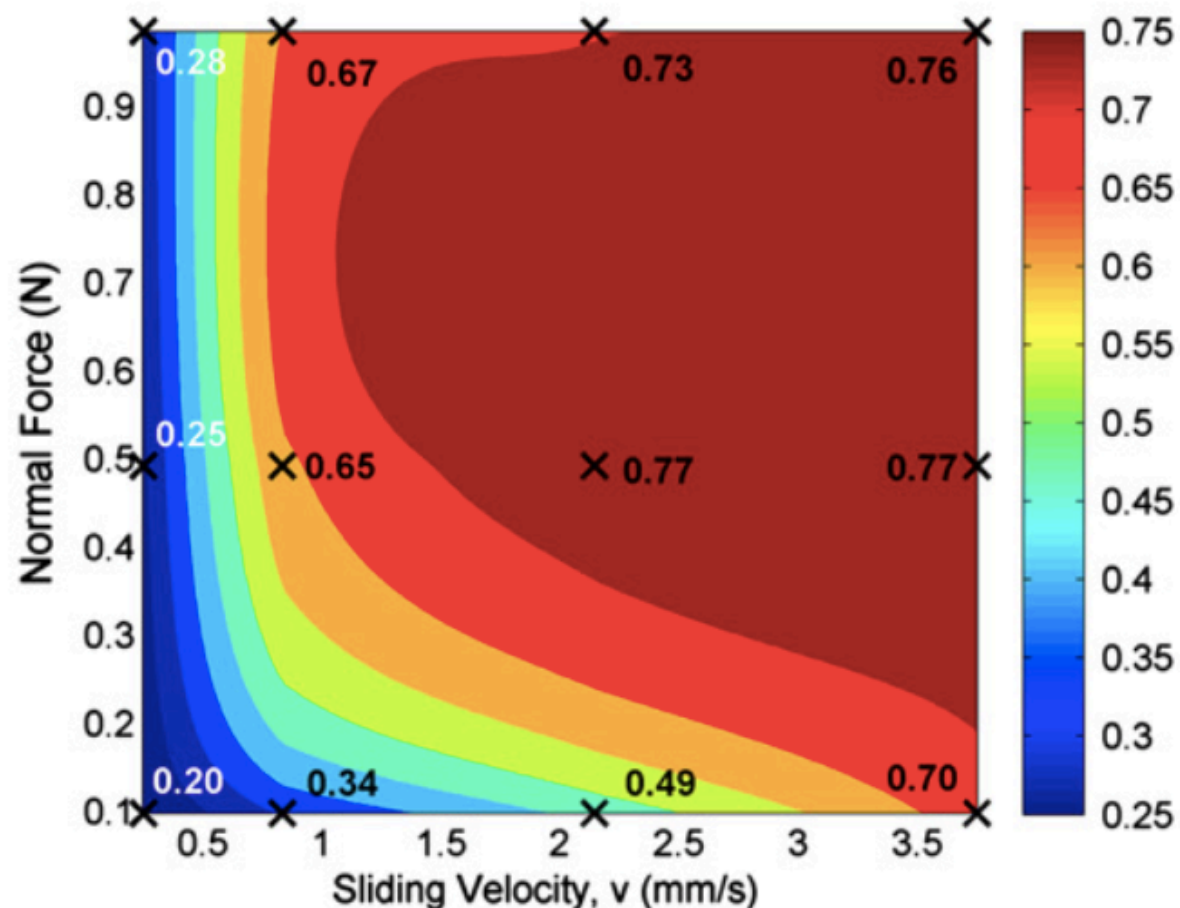
Ni-W demonstrated improved thermal stability...what about mechanical?

Ni-W: Previous Wear Study

Microstructural and mechanical properties of Ni–W electrodeposits.					
W content (at.%)	Average XRD grain size (nm)	Average TEM grain size (nm)	Hardness (GPa)	Wear volume (μm^3)	Friction coefficient
3.0	47	25	4.0	9.49×10^6	0.63
6.0	30		5.6	7.40×10^6	0.67
8.2	26		5.9	5.88×10^6	0.61
12.5	15		6.6	5.12×10^6	0.65
15.7	9	6	6.8	5.06×10^6	0.66
18.2	6		6.9	4.03×10^6	0.65
22.9	5		7.1	3.79×10^6	0.60
27.9	3		7.1	2.77×10^6	0.66

5N applied load, 150 mm/s → High friction measured across range of initial compositions and hardness values

Friction Transition in Ni-20Fe



Data collected *via* unidirectional sliding in inert environment

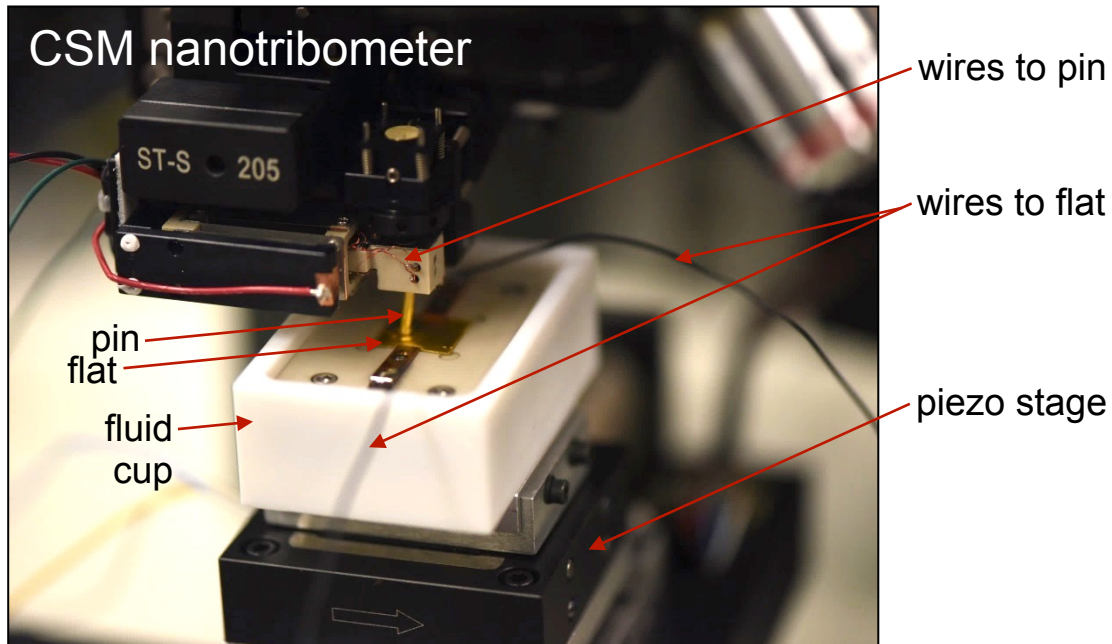
Friction coefficients measured plotted as X's

Contours by cubic interpolation

Low to high friction transition observed for increased normal force and sliding velocity

Is there a window of microstructural stability under wear for Ni-W?

Experimental Method



Test parameters:

- 1 mm/s sliding speed
- Bidirectional sliding (to/from = 1 cycle)
- 1.6 mm **sapphire** ball (chosen to match $H=9\text{GPa}$)
- 2 mm track
- In air (10% humidity)

Three contact forces:

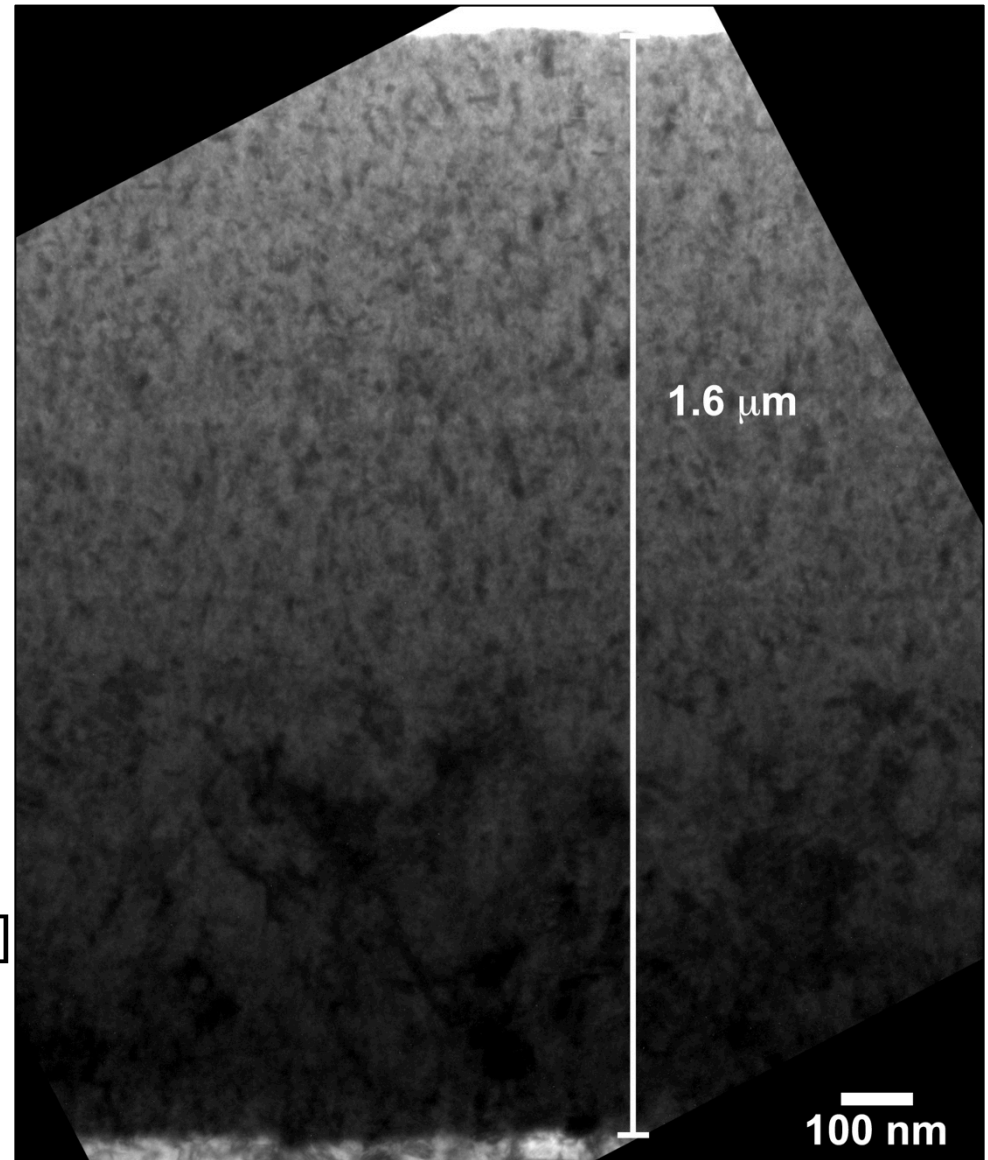
- 1 mN
- 10 mN
- 1000 mN

Goal to study microstructural stability under wear over a range of loads and cycles

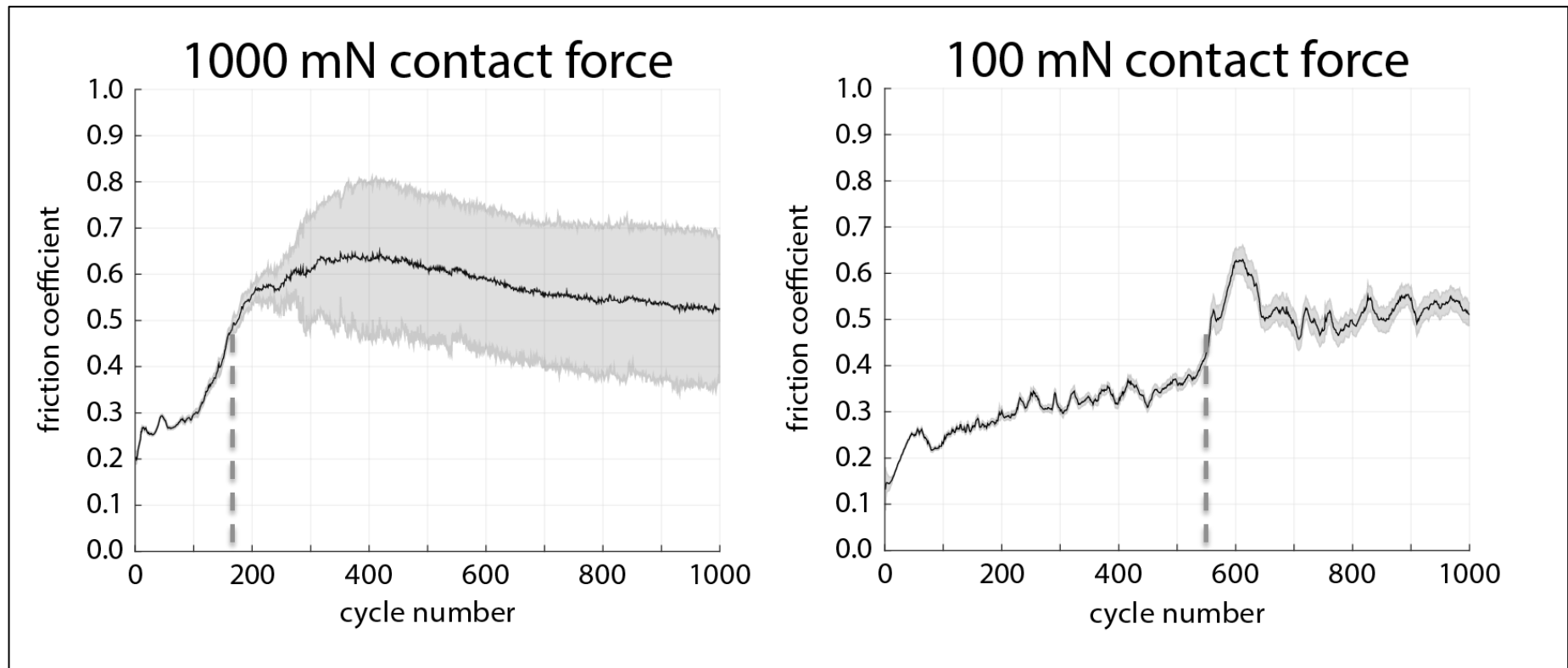
Cross-sectional samples for each wear track prepared for TEM via FIB milling

Initial Microstructure: Ni-40 wt.% W Sandia National Laboratories

- Electrodeposited Ni-40W, on brass substrate
- Film thickness of 1.6 μm
- Starting grain size of $5.2 \pm 0.2 \text{ nm}$, via XRD
- Demonstrated stability of grain size over 24 hours at up to 500 $^{\circ}\text{C}$ [Detor & Schuh]

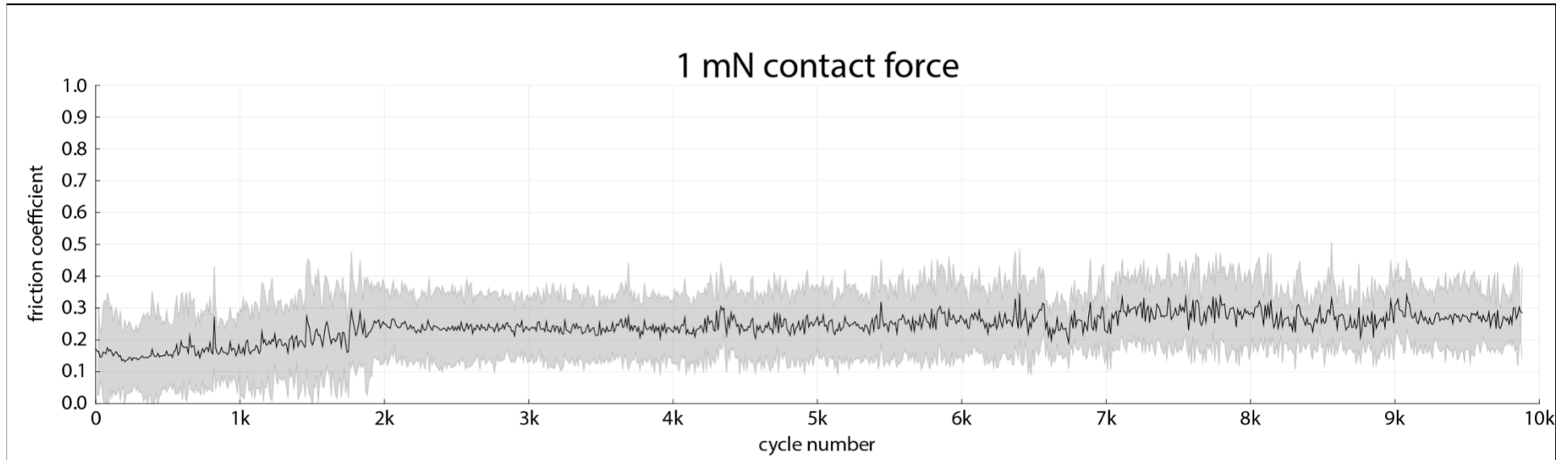


Higher Contact Force Results



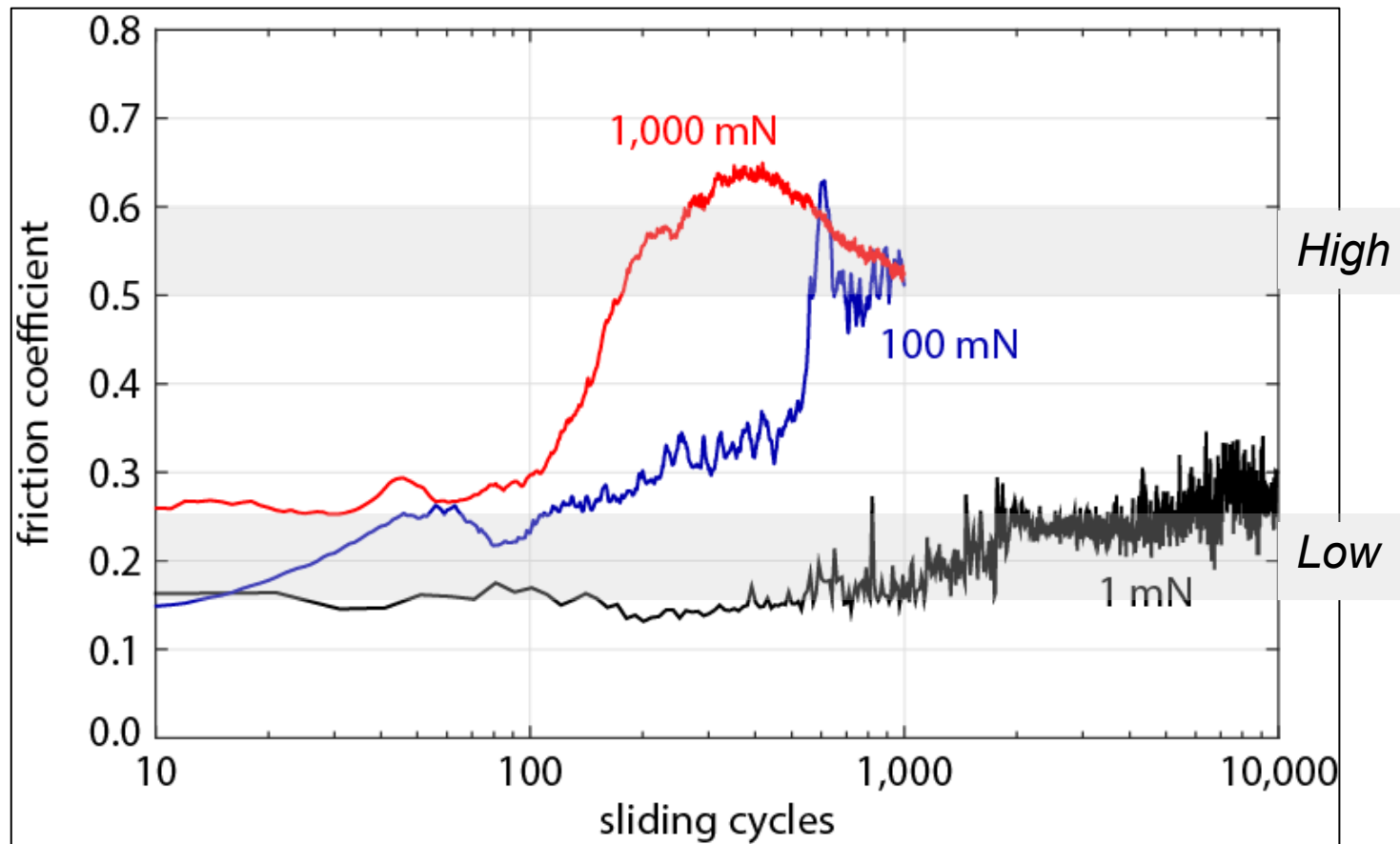
**For higher applied contact forces,
see transition from low COF (0.15-0.25) to high COF (0.5-0.6)
within hundreds of cycles**

Low Contact Force Results



**For the lowest applied contact force case,
friction coefficient remains low (0.15-0.25) for test duration
over 10,000 cycles**

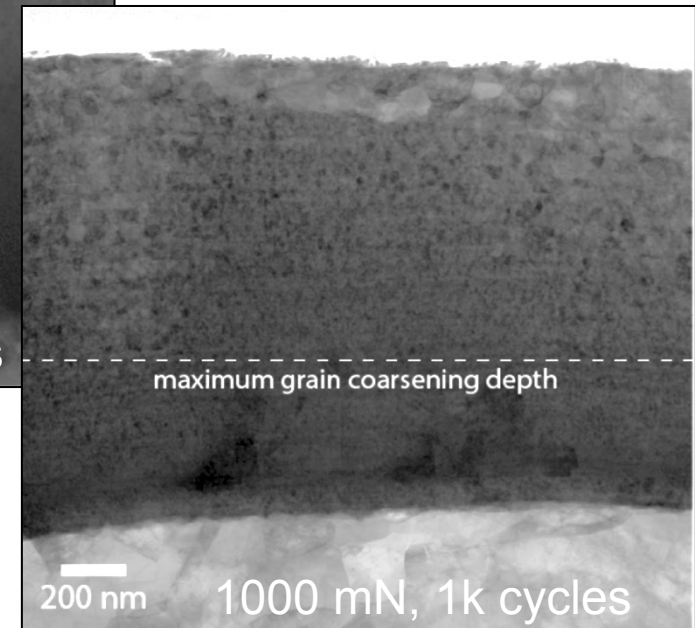
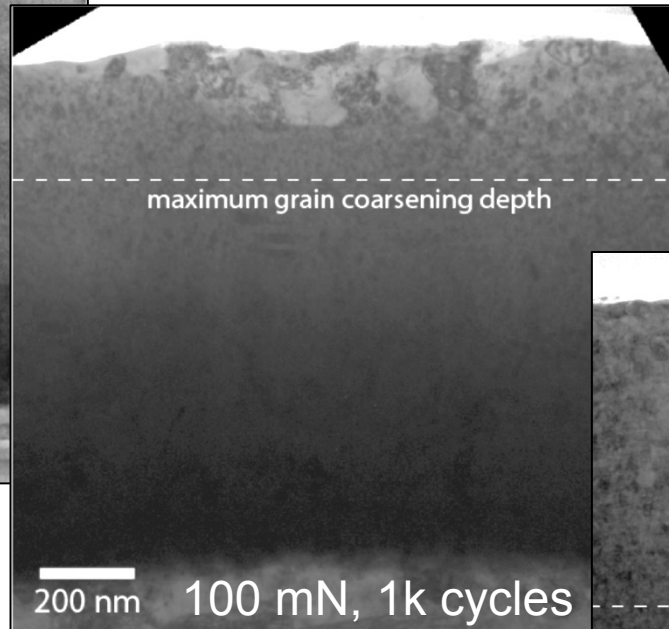
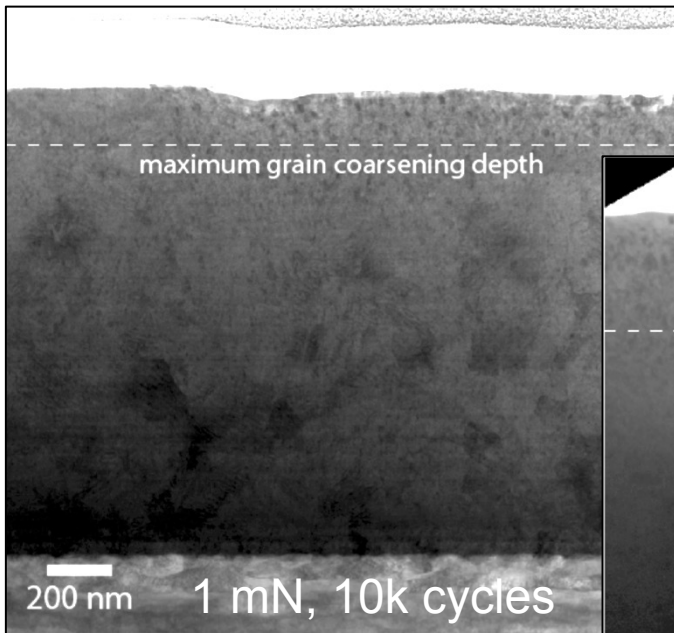
Friction Response as a Function of Contact Force for Ni-40W



- Friction coefficient low, 0.15-0.25, for first 100 cycles for all
- Transition to high friction, 0.5-0.6, for all but the 1 mN case

Microstructure in Ni-W Wear Tracks

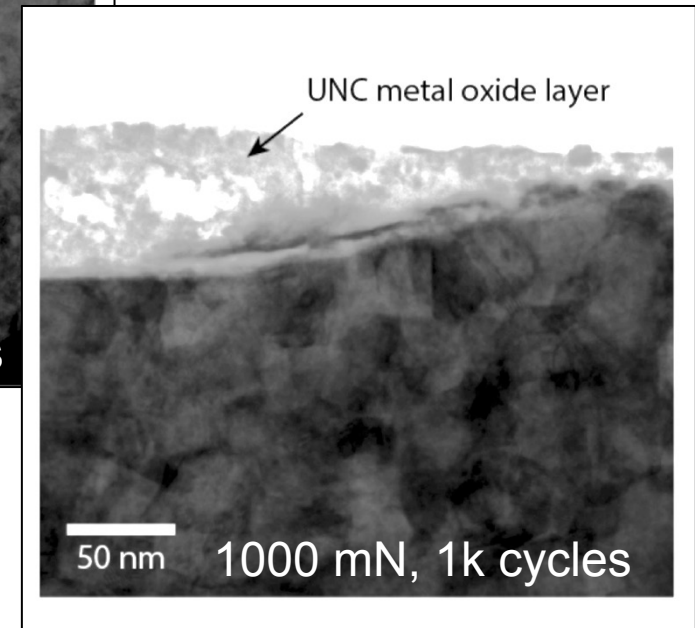
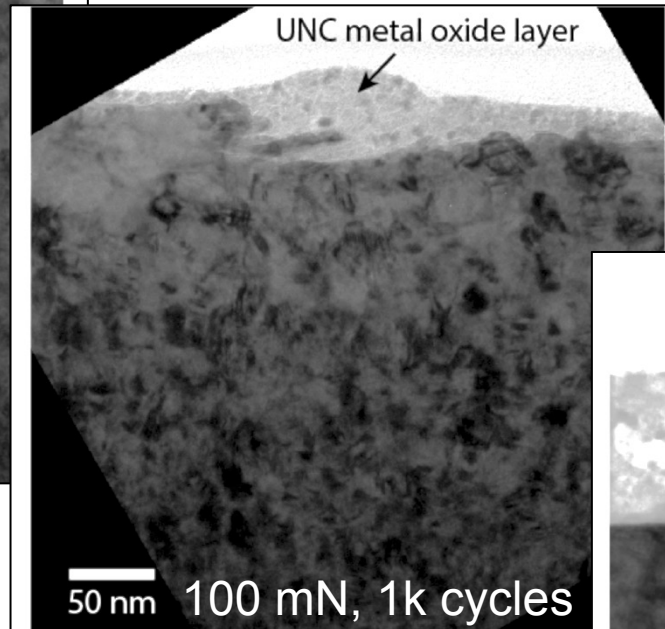
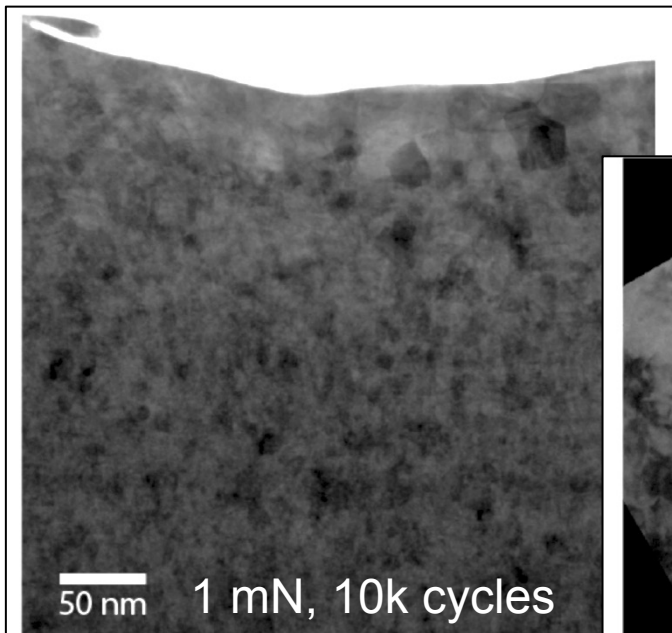
- Cross-sectional TEM shows microstructural evolution in each wear track



**Grain coarsening depth increases
with increasing contact force**

Microstructure in Ni-W Wear Tracks

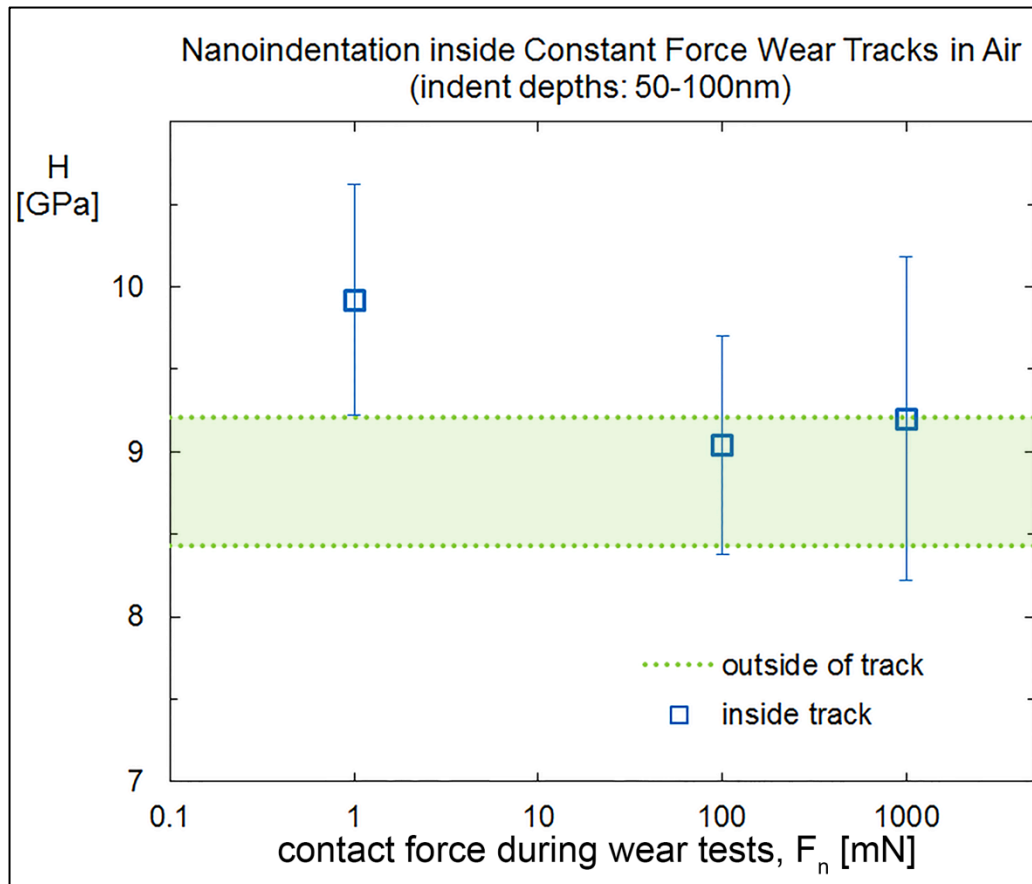
- Presence of metal oxide layer with increased wear



Max grain size increases with increasing contact force

Is the low friction hardness driven?

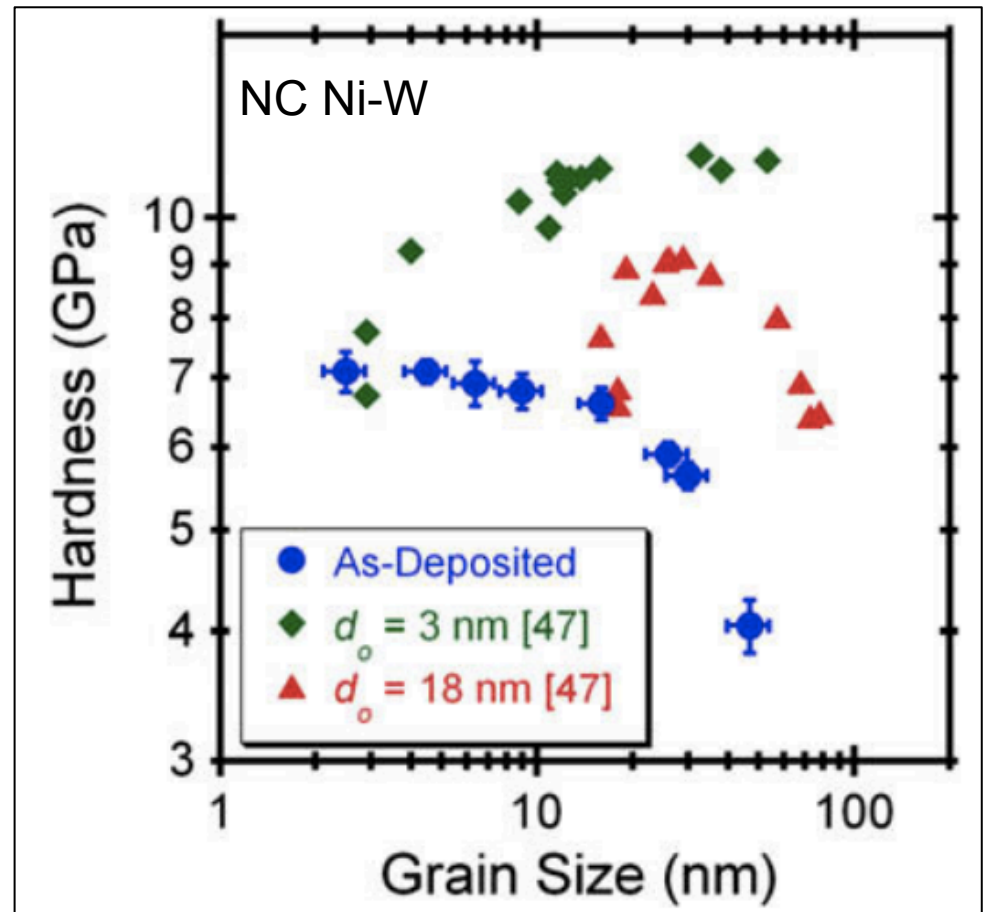
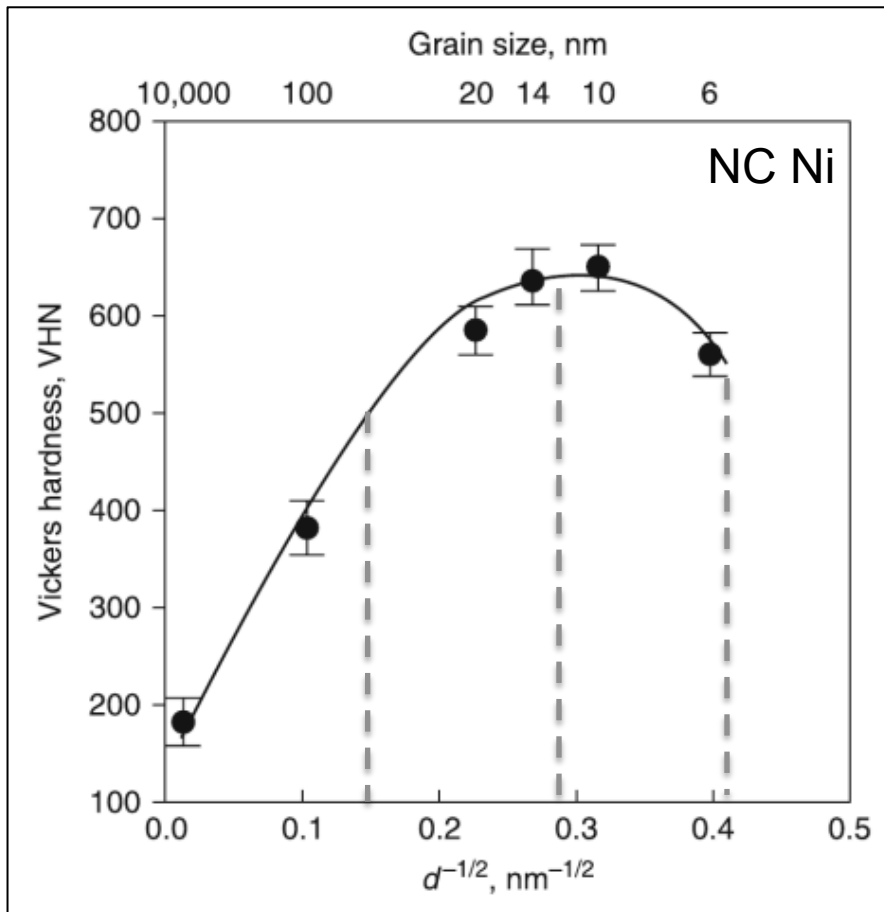
Increase in Hardness for 1mN Track



- Increase in hardness (13%) for 1 mN wear track
 - In comparison to higher force tests *and* to parent material
- Parent material
 - ~ 5nm grains
- 100 and 1000 mN track
 - ~ 50-100 nm grains
- 1 mN track
 - ~ 10-20 nm grains

Higher hardness in 1mN track consistent with low coefficient of friction – but why harder than as-dep'd?

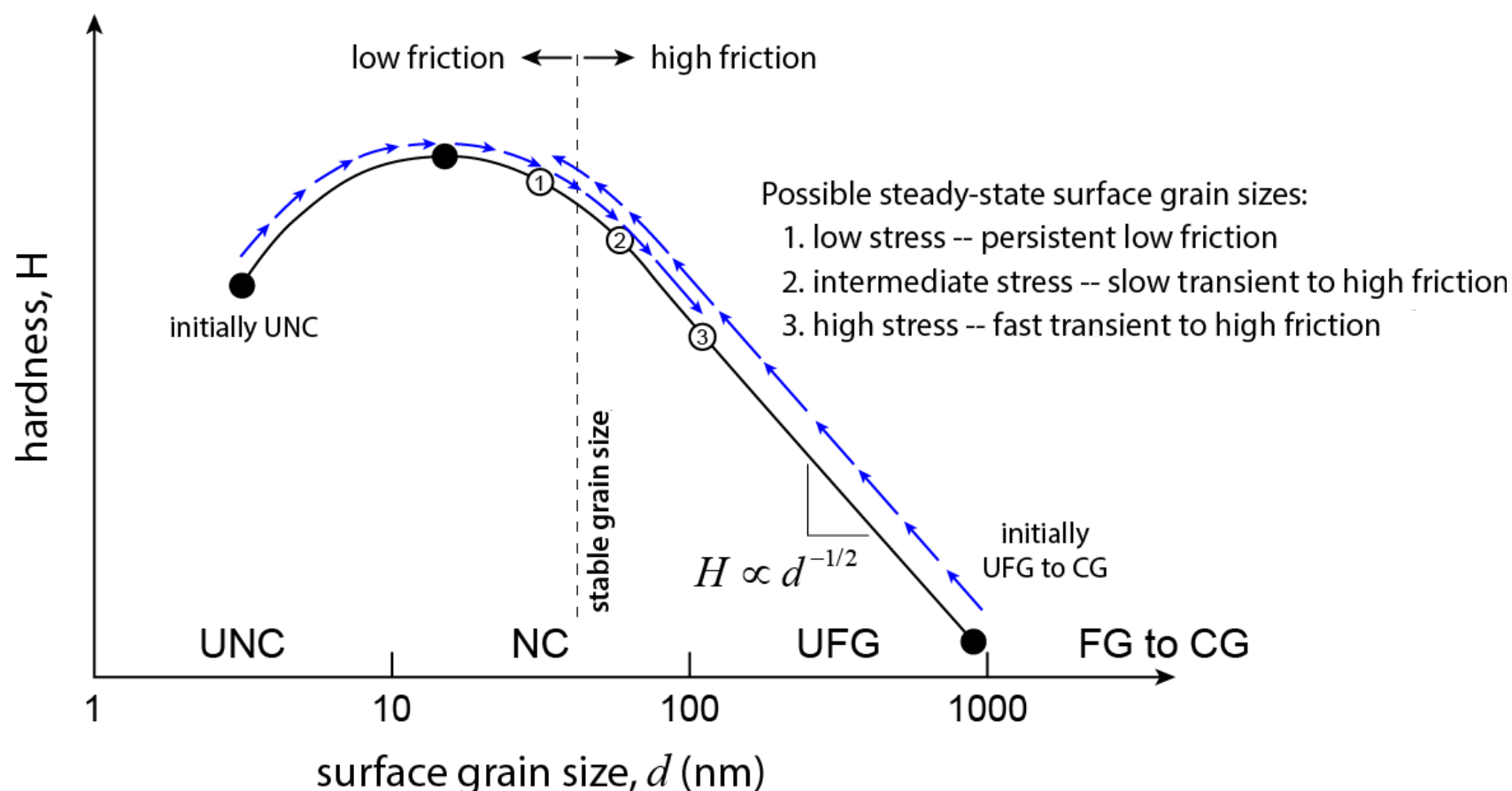
Hardness for 1mN Track > As-Dep'd



Higher hardness of evolved microstructure, compared to as-deposited microstructure, consistent with previous data

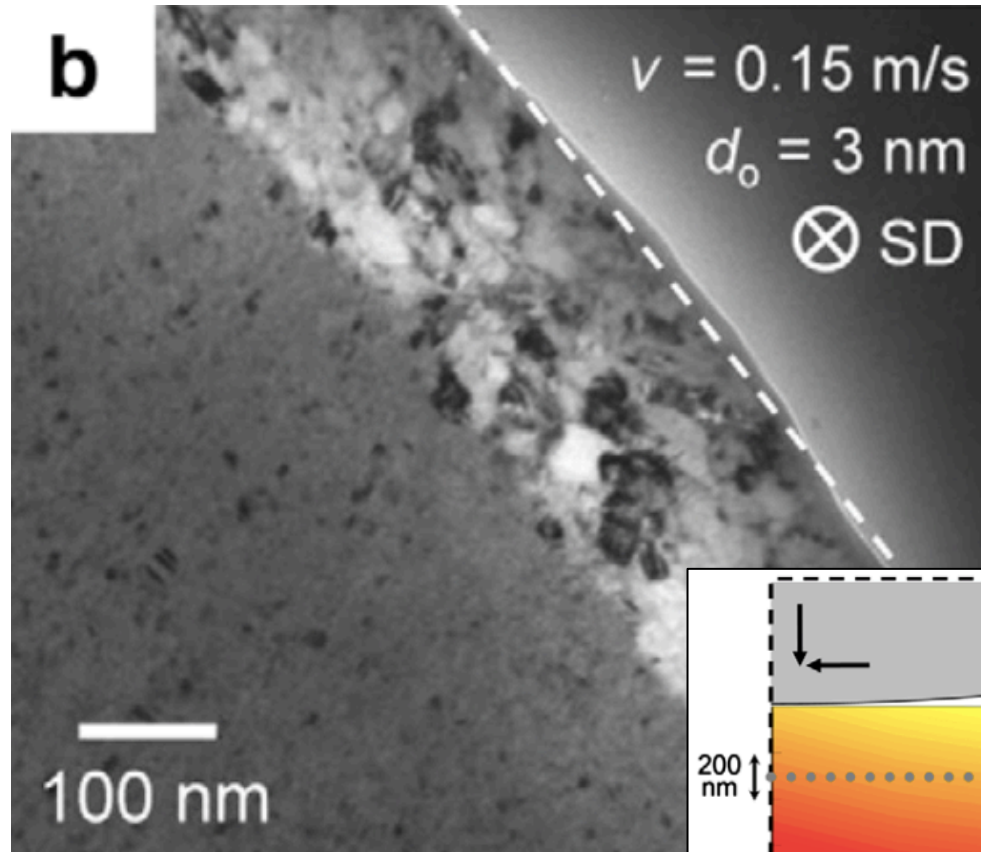
How to define a friction transition?

Stress-Dependent Stability?

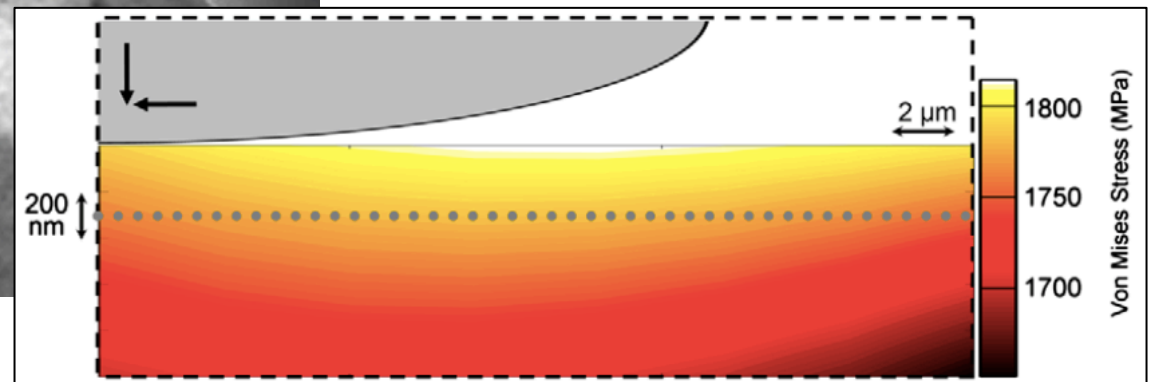


If true, then at the 'right' stress, you would drive ultra-NC material to be NC...and coarse grains to be NC!

Evidence for Grain Coarsening under Wear

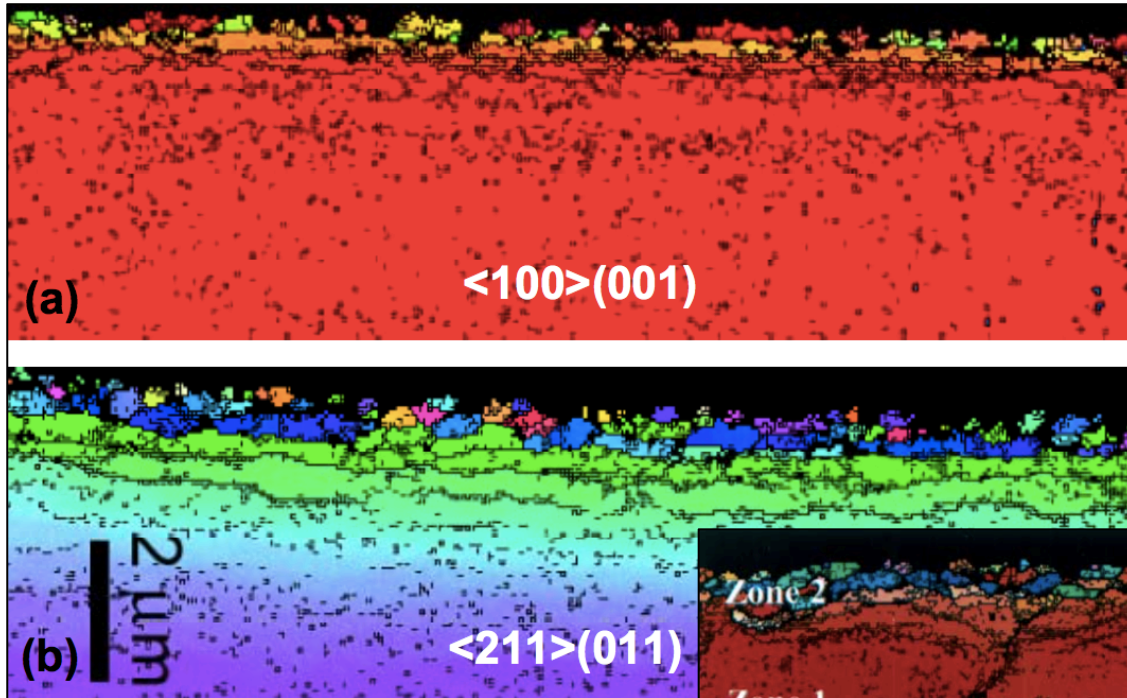


- Grain coarsening observed in previous study of Ni-W under sliding wear
- Coarsening depth correlated to depth of maximum von Mises stress

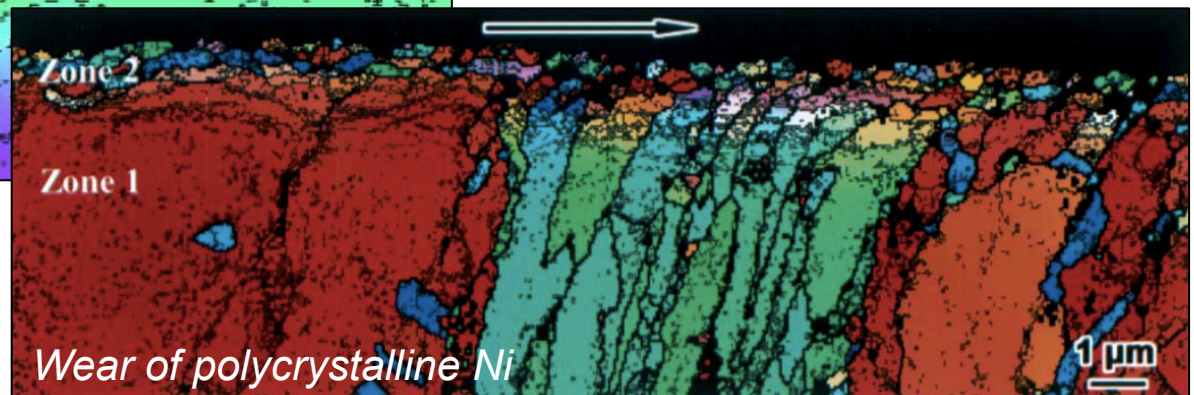


**Stress-driven grain coarsening seems intuitive,
but is grain *refinement* possible?**

Evidence for Grain Refinement under Wear



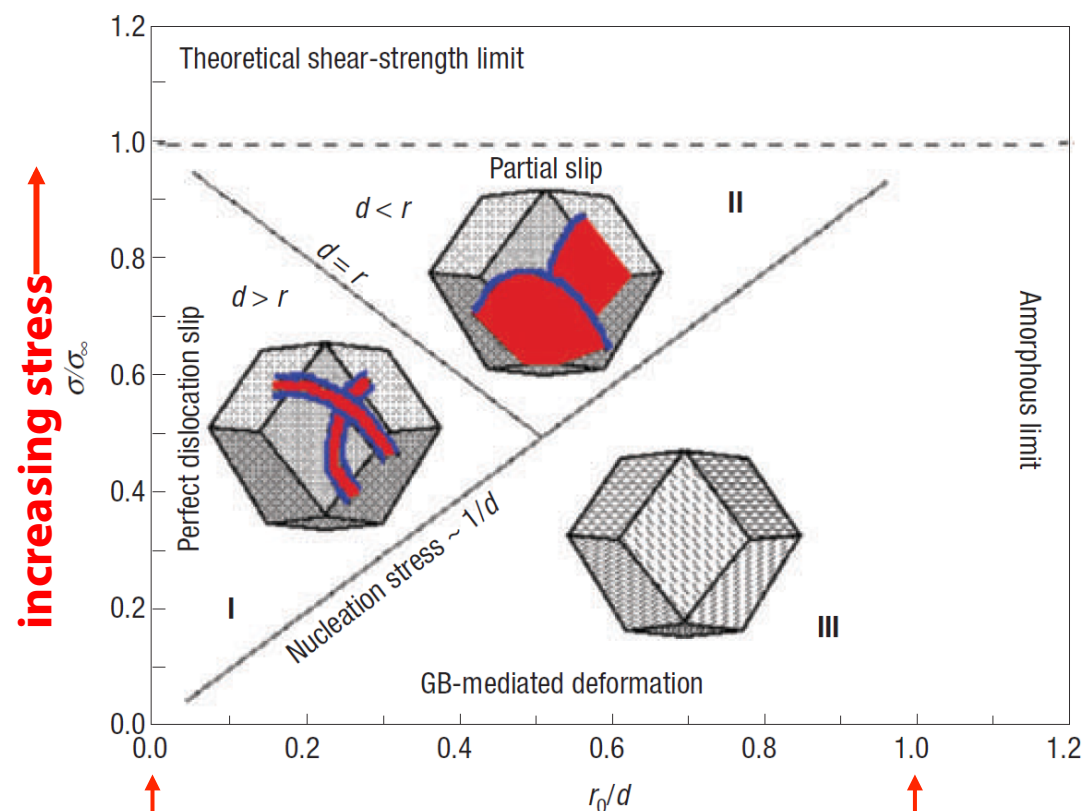
- Electron backscatter diffraction data of wear track cross-sections in Ni
- Grain refinement observed at wear track surface in both cases



Formation of ultrafine grains observed at wear track surfaces in single crystal and polycrystalline Ni

Can we Define a Stress-Dependent,
Stable Grain Size under Wear?

Polycrystalline Plasticity Mechanisms



Hypothesize that low friction stability occurs when microstructure supports grain boundary mediated deformation processes

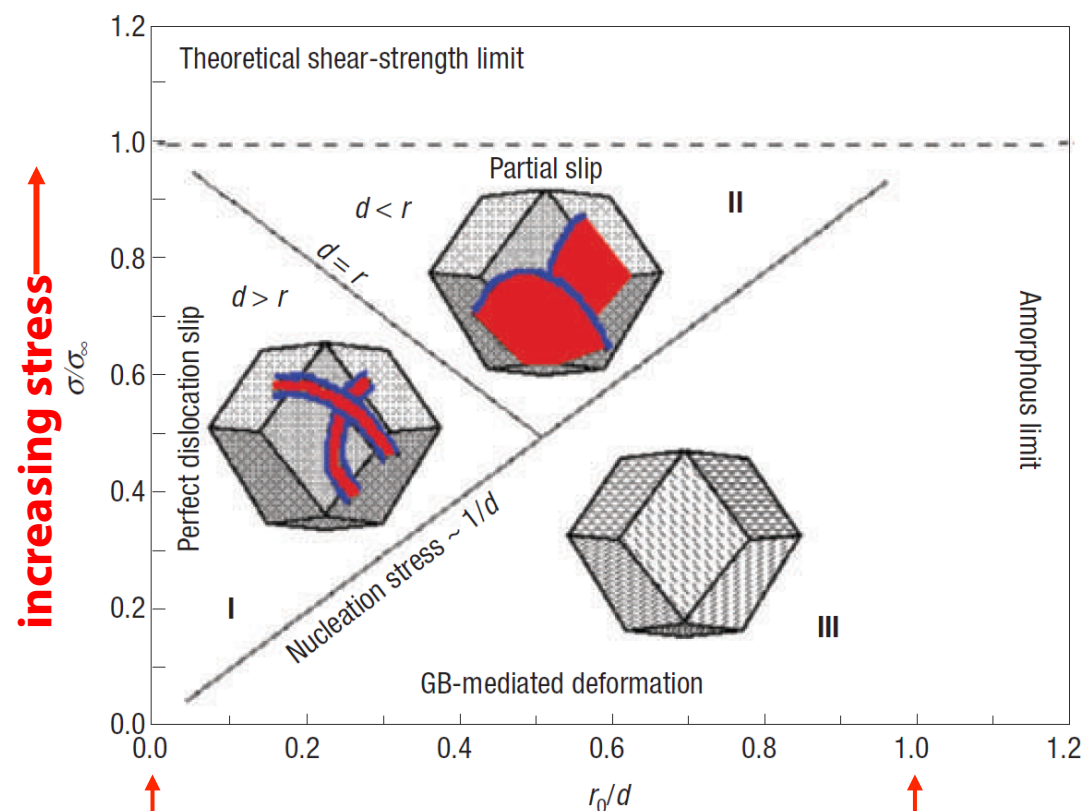
↑
grain size
goes to
single crystal

←
increasing
grain size

↑
Minimum grain size
(peak H-P) $d = r_0$

Dominant plasticity mechanism linked to grain size AND stress

Polycrystalline Plasticity Mechanisms



Hypothesize that low friction stability occurs when microstructure supports grain boundary mediated deformation processes

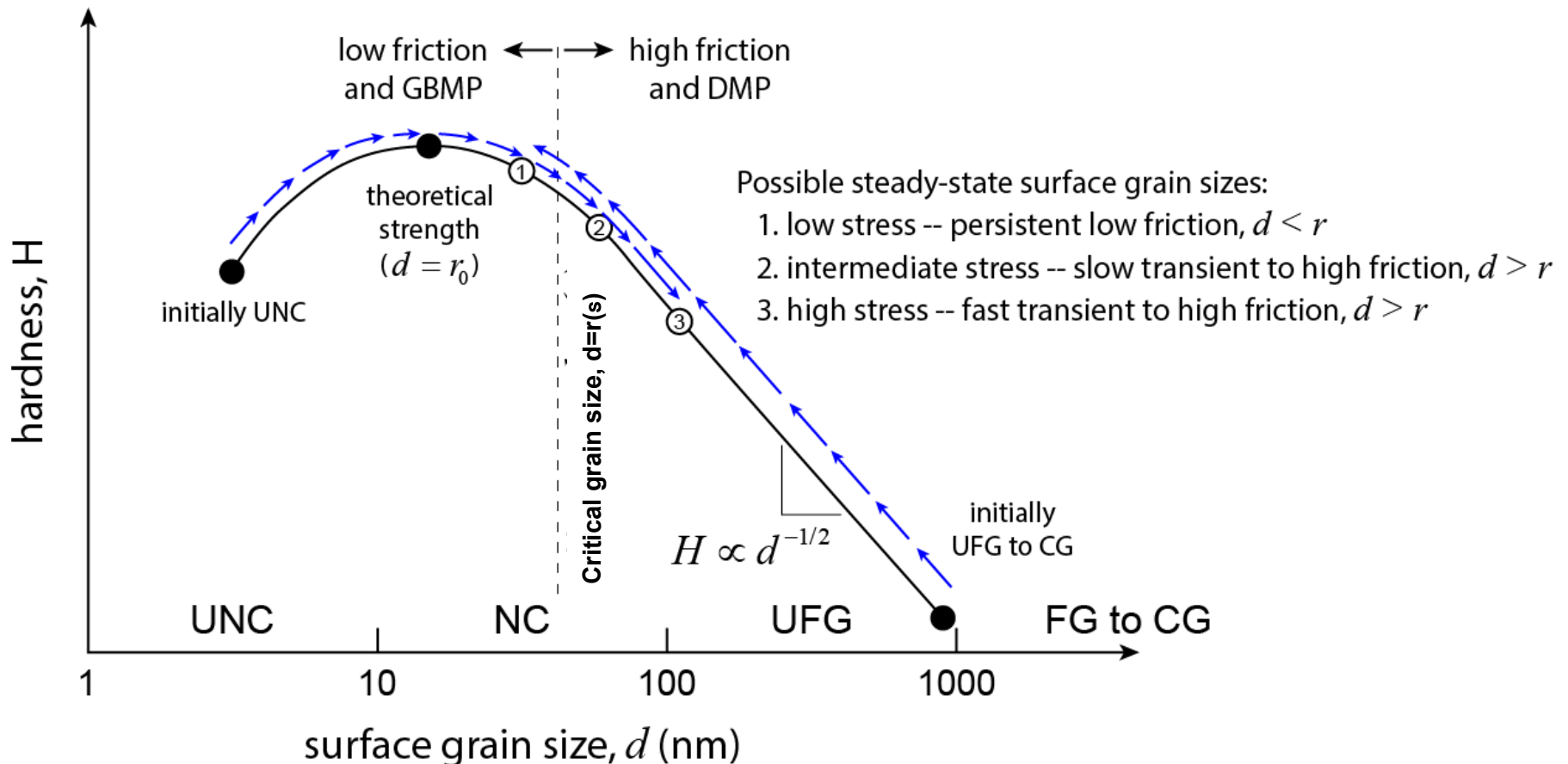
↑
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↑
Minimum grain size
(peak H-P) $d = r_0$

Dominant plasticity mechanism linked to grain size AND stress

Stress-Dependent Stable Grain Size



Critical grain size hypothesized to be equal to the stress-dependent dislocation splitting distance

Stress-Dependent Splitting Distance

Stress-dependent splitting distance:

$$r = \frac{r_0}{1 - \sigma_a / \sigma_\infty}$$

Equilibrium (zero stress) dislocation splitting distance:

$$r_0 = \frac{(2 + \nu) G b^2}{4\pi (1 - \nu) \gamma_{sf}}$$

Theoretical strength (grain size where Hall-Petch reaches max):

$$\sigma_\infty = \frac{2\gamma_{sf}}{b}$$

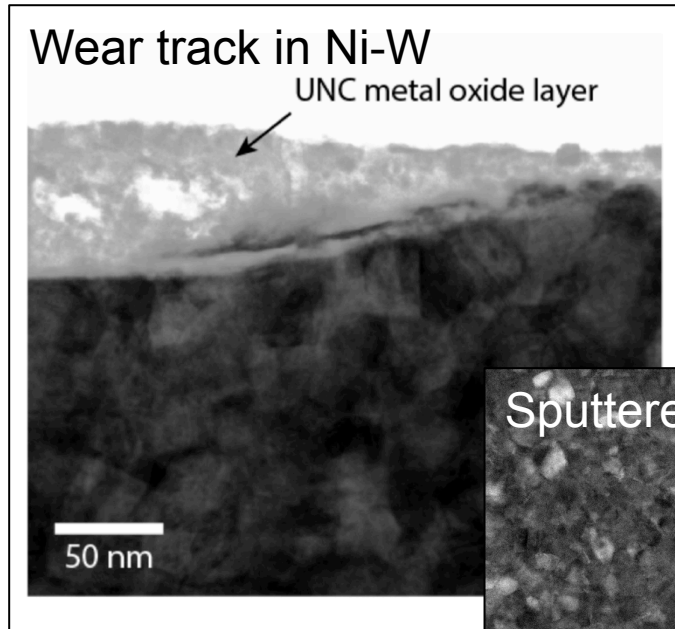
- Function of zero-stress, equilibrium splitting distance, and the ratio of applied stress (to theoretical strength
- Aside from applied stress, all other parameters are materials dependent (G, b, ν , SFE)

Hamiltonian applied stress (von Mises surface stress):

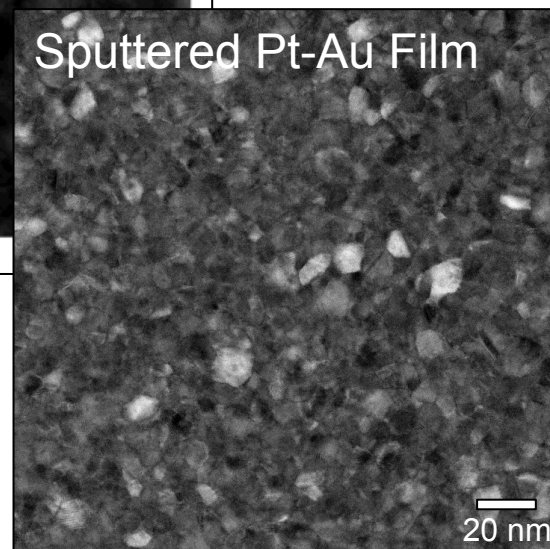
$$\sigma_\infty = \frac{3F_n}{2\pi a^2} \left[\frac{1 - 2\nu}{3} + \frac{(4 + \nu)}{8} \pi \mu \right]$$

Normal forces during wear above 5-10 mN would drive evolution beyond critical 37 nm grain size in Ni-W, consistent with our data

Future Work: Isolate Solute Effects



- Recall the surface oxide layer...
- Interested in better isolating the contribution of solute segregation on mechanical stability of NC alloys

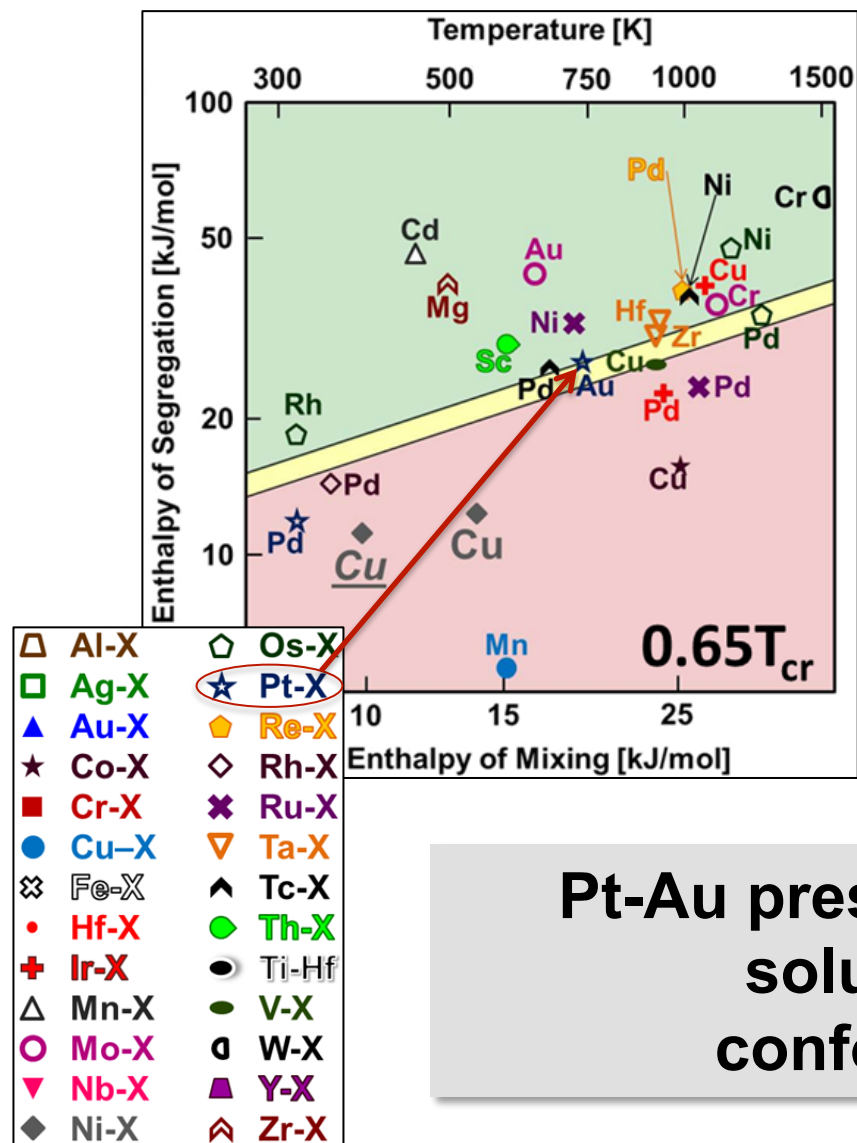


- Pt-Au synthesis routes optimized
- As-deposited grain size of 5-6 nm

Studies in the noble metal binary system of Pt-Au are underway for thermal & mechanical stability

Selection of Pt-Au

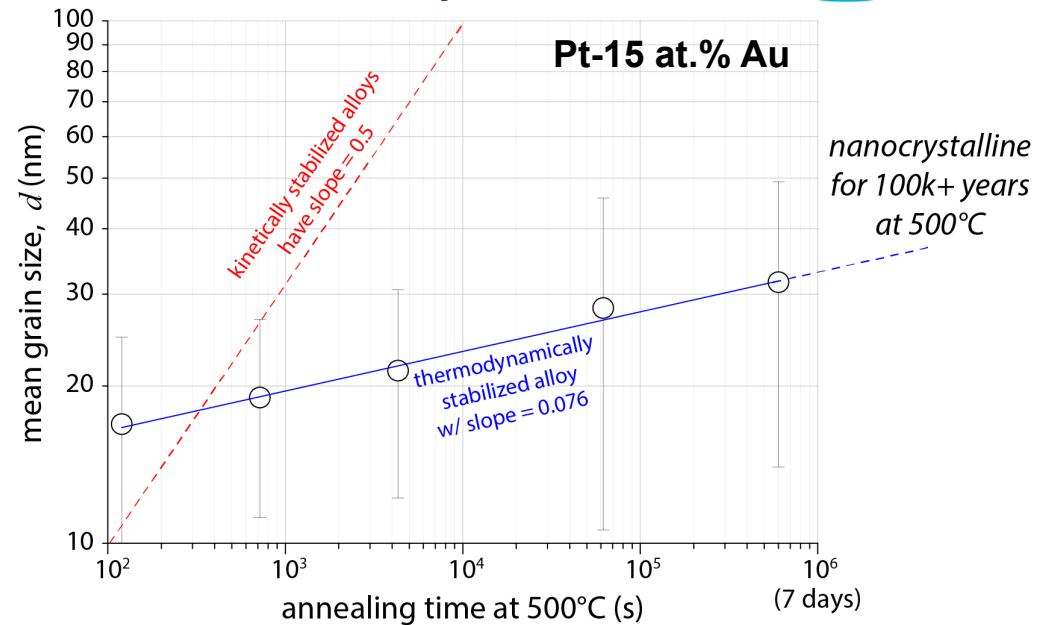
- Alloy selection driven by predictions of Murdoch & Schuh
- Wanted to avoid oxidation:
 - No oxidation in air
 - Chemically inert elements
- Pt-Au predicted to fall just at boundary of thermally-stable, solute stabilized region



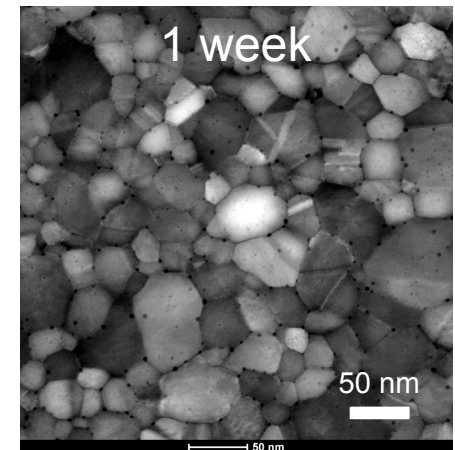
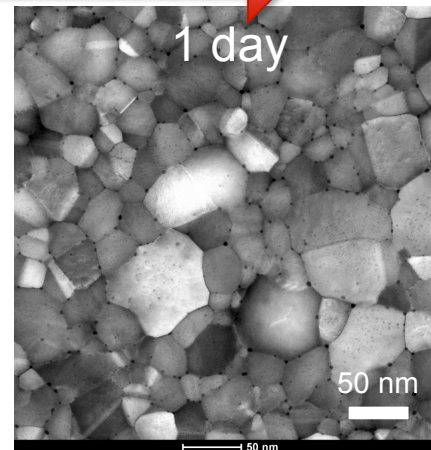
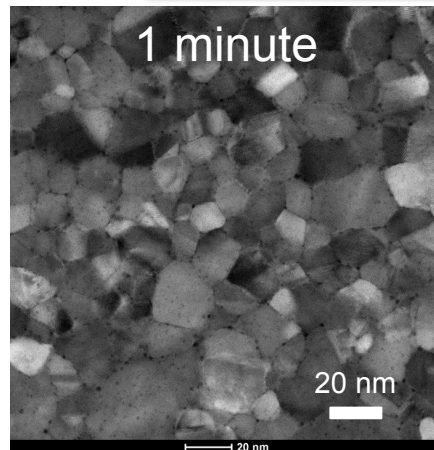
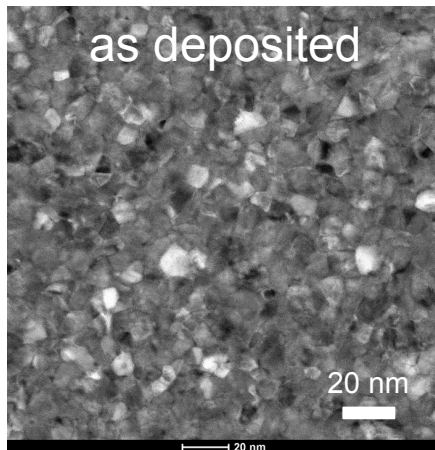
Pt-Au presents an opportunity to study solute segregation without confounding effects of oxide

Evidence of Thermodynamic Stability

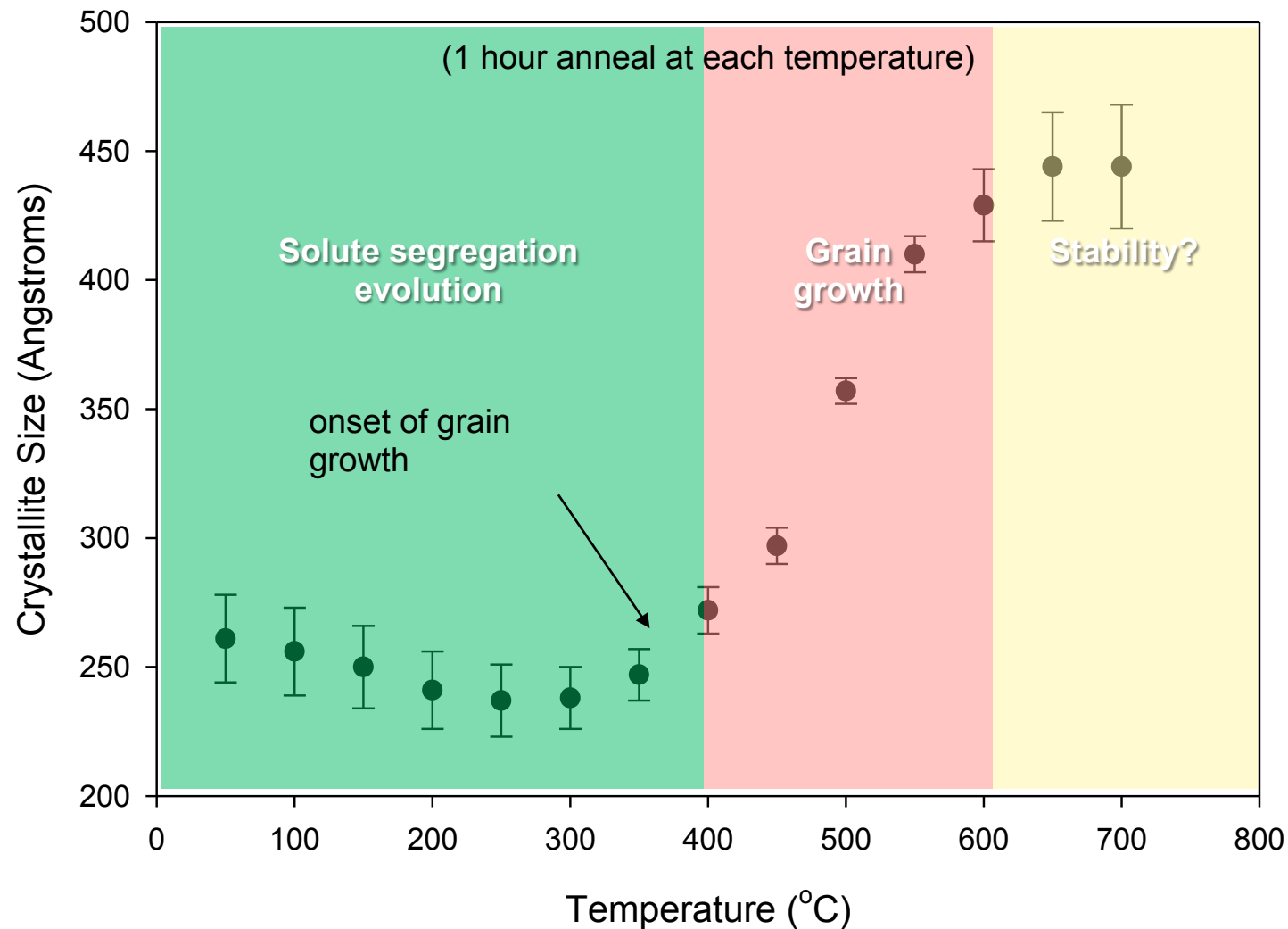
- Constant temperature interrupted TEM annealing at 500°C, free-standing sputtered **Pt -15 at.% Au** films lifted from salt crystals
- Abnormal grain growth observed
- Grain growth trend does not follow $\text{time}^{1/2}$ trend (characteristic of kinetic stabilized alloys)



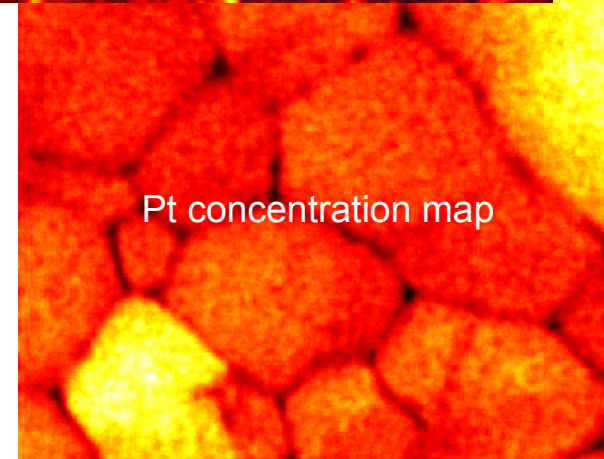
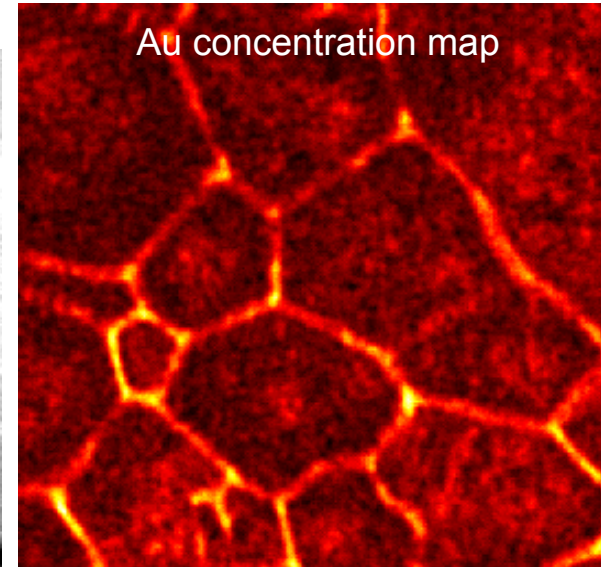
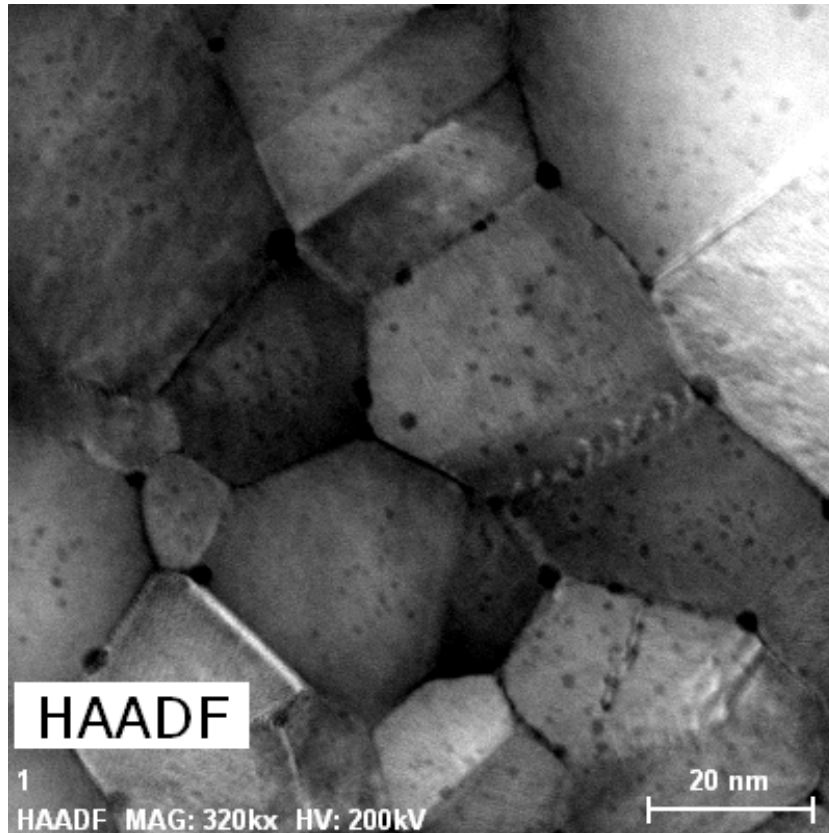
500°C anneal ($T/T_m \sim 0.5$)



Evolution of 10 μm thick Pt-Au Films



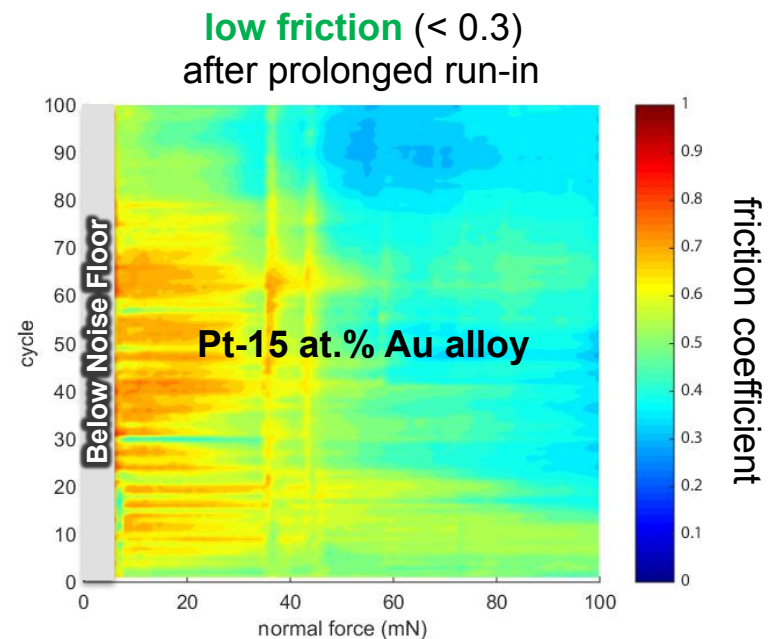
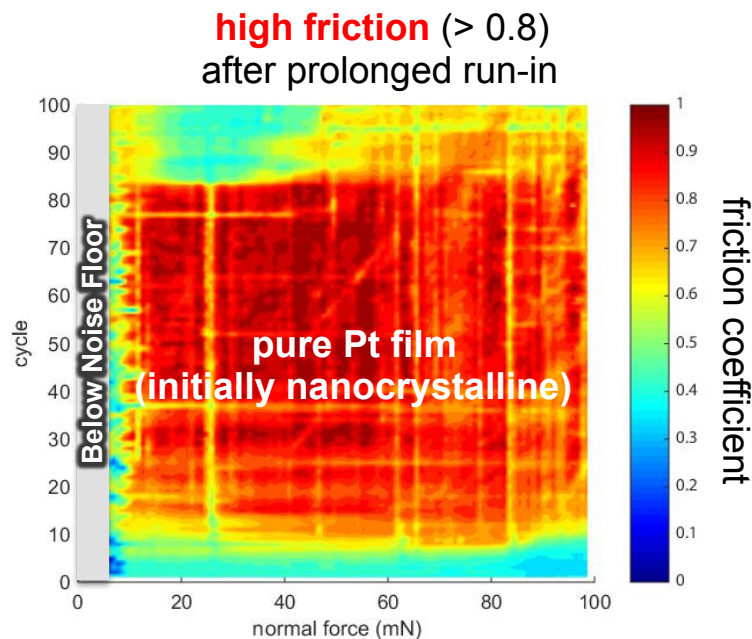
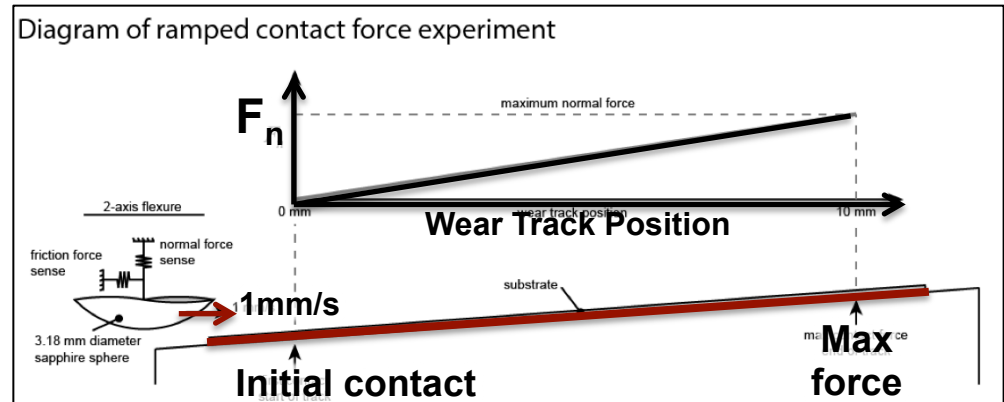
Preferential Segregation of Au at Triple Junctions



Tribological Testing – Evidence of Mech. Stability

(Right) Contact force is ramped along the length of the wear track with continuous friction measurement:

(Below) Using a Au-alloy tip rastered on pure and alloyed Pt we measure the following friction data:

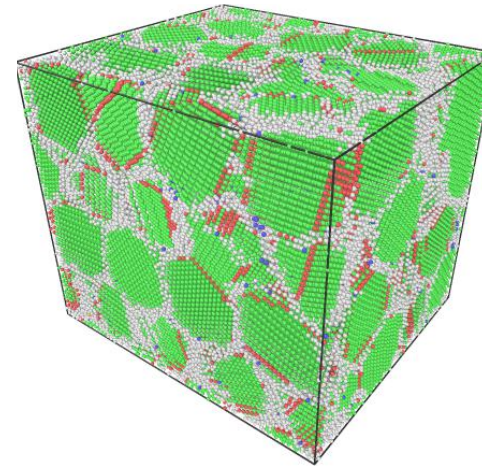


Pt-Au films showed low friction & negligible wear

MD Supports Shows High Thermal Stability

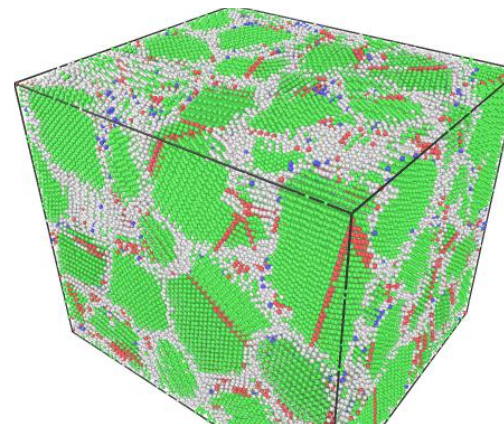
- Potentials for Pt-Au completed and vetted, results shown here – Pt-Au is highly stable, little change in microstructure
- Pt-Pd potentials completed, no preliminary data yet
- Pure Pt shows significant grain coarsening
- Capability to investigate stress-induced grain growth via MD has been developed

initial microstructure



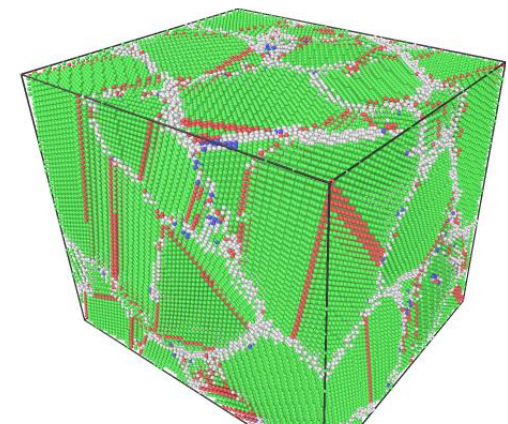
after annealing 4 ns at 950°C

Pt-12 at.% Au alloy



minimal coarsening

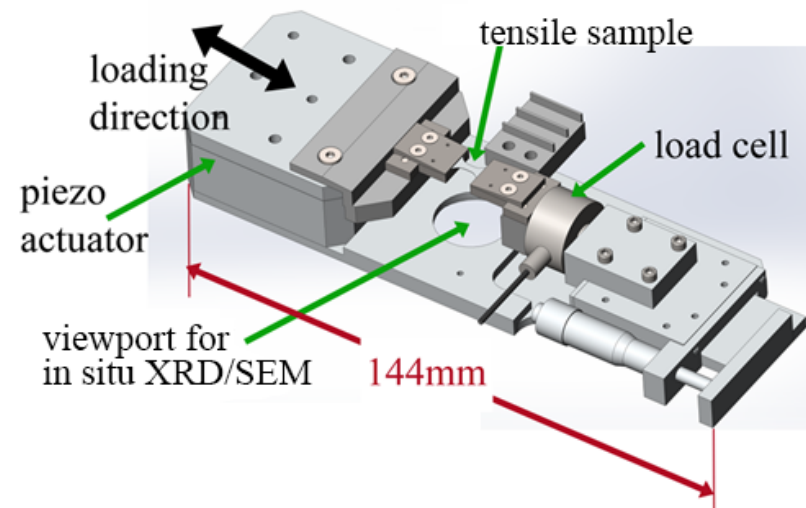
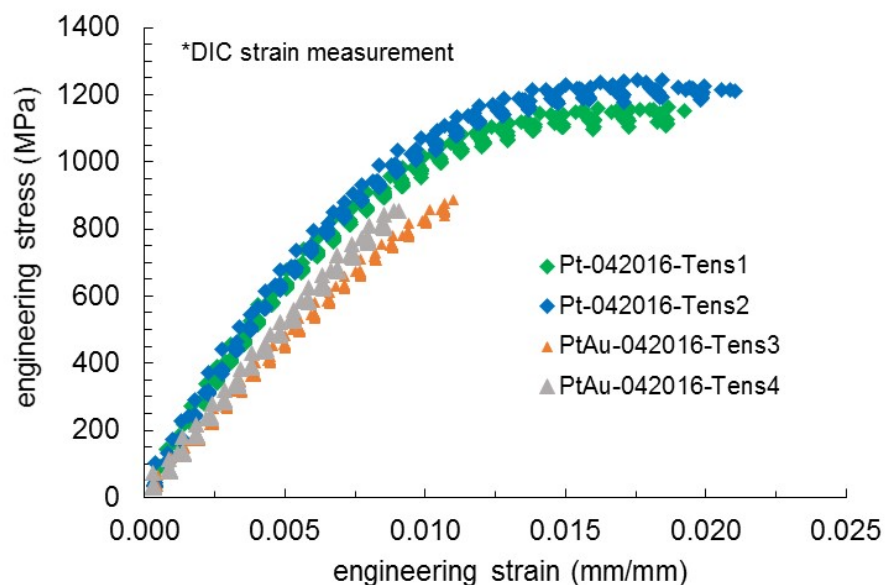
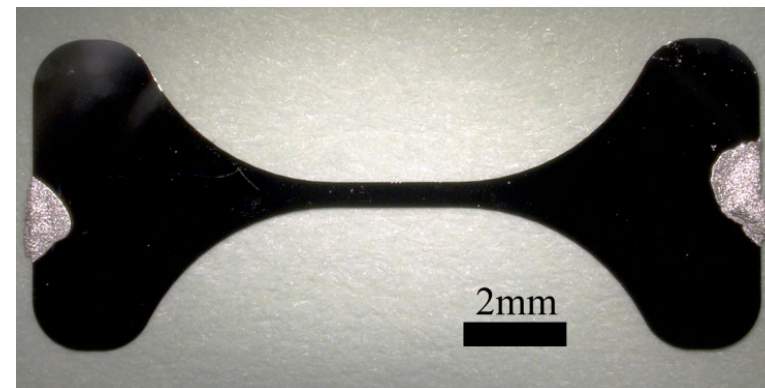
pure Pt



significant coarsening

Tensile Testing Underway – Preliminary Data Here

- Developed method for fabricating free-standing “thin film dogbones” (10 μm thick) via laser cutting of sputtered films
- Micro-tensile fatigue tests underway



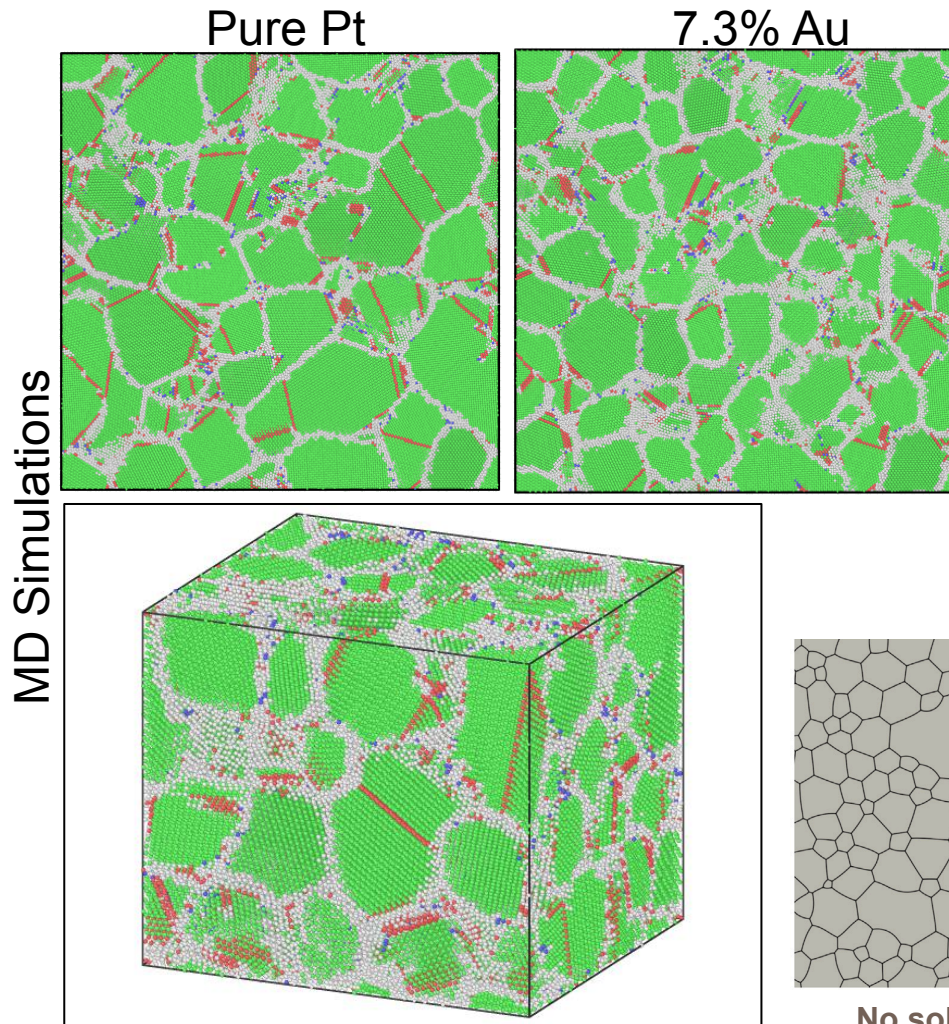
Summary

- Microstructural stability of Ni-W studied under sliding wear over a range of contact forces and cycles
 - Significant grain coarsening observed for 100 and 1000 mN, transition to high friction in 100s of cycles
 - Minimal grain coarsening for 1 mN, measured hardness increase and no transition to high friction to *10000* cycles
- Proposed presence of a stress-dependent stable grain size in nanocrystalline alloys under wear
 - Hypothesize low friction, stable microstructure in grain-boundary mediated plasticity regime
 - Potentially related to dislocation splitting distance
- Future work underway to:
 - Isolate solute segregation effects
 - Develop predictive framework for mechanical stability

Does Thermal Stability Lead to
Stability under Wear?

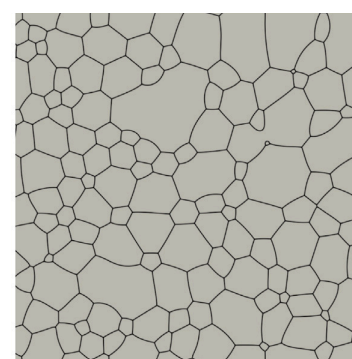
What Do We Know about Stability of
Nanograins under Wear Anyway?

Future Work: Pair with Modeling



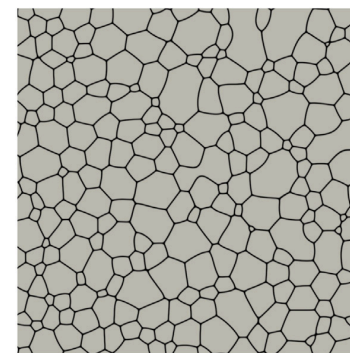
Combining experiments with modeling to further explore:

- Role of solute segregation in determining stability
- Competition between thermodynamics and kinetics
- Contributions of other variables (e.g. boundary type, film stress)

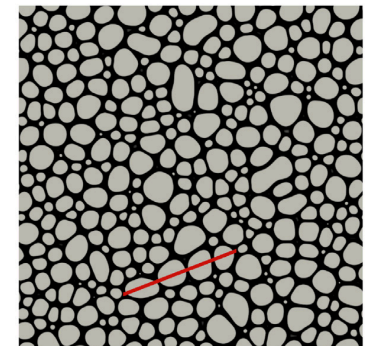


No solute

$C_{\text{solute}} = 0.20$



$C_{\text{solute}} = 0.35$



Phase Field Model

Consider Stability

